

EMISSION PROPERTIES OF PtSi-COATED SILICON NANOCONES IN THE TRANSITION REGIME

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Physics of Interfaces and Nanomaterials (PIN)

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MCEC

Netherlands Center for Multiscale Catalytic Energy Conversion

**UNIVERSITY
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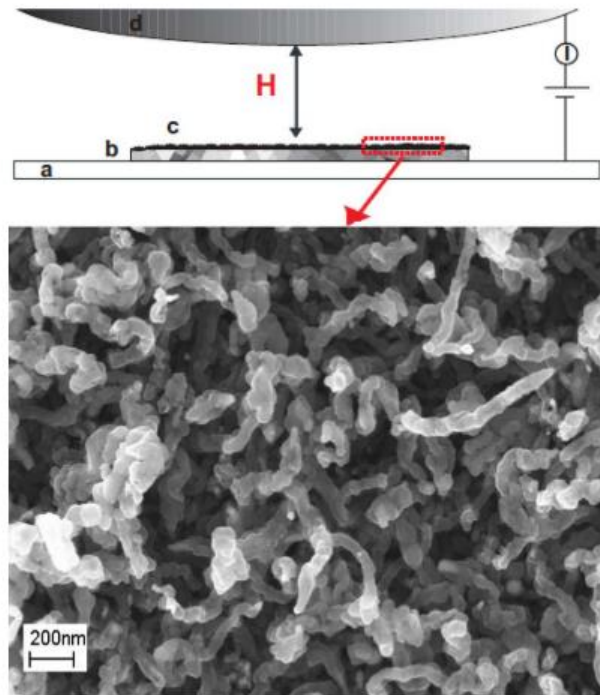
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Contents

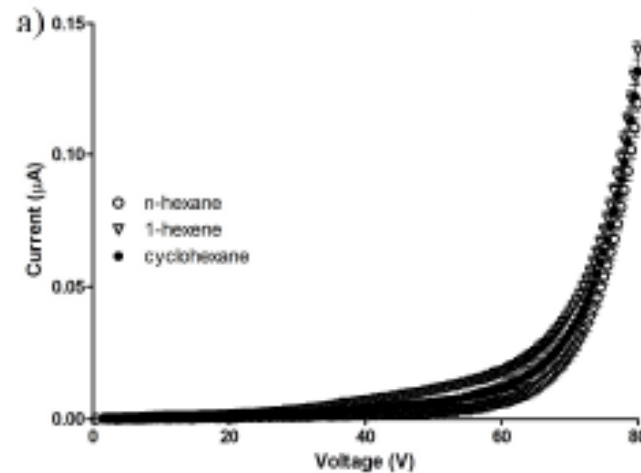
- Motivation
- Fabrication overview
- Experimental setup
- Results

Motivation

Using a field emitter for performing chemical reactions



A. Ağır, et al., "Charge injection from carbon nanofibers into hexane under ambient conditions," 2011.



Solvent type	9,10-dihydroanthracene %	anthraquinone %
Apolar (with or without proton donator)		
n-hexane	None	None
n-hexane + 5% _{vol} ethanol	None	None
n-hexane + 10% _{vol} ethanol	None	1.2
n-hexane + 25% _{vol} ethanol	None	4.3

M. (2016). Morassutto, "Flow chemistry using field electron emission from SiNW's," in *Cold field emission in microreactors to perform chemical reactions*, 2016

Fabrication Overview

General process flow: Additive hybrid Lithography

Key features

- Combination of conventional and Displacement Talbot photolithography techniques to form etch mask.
- Yields nanoscale patterning at the macroscale.
- Continuous mode reactive ion etching for smooth sidewalls (no scallops)
- Platform for field emitter electrodes device integration

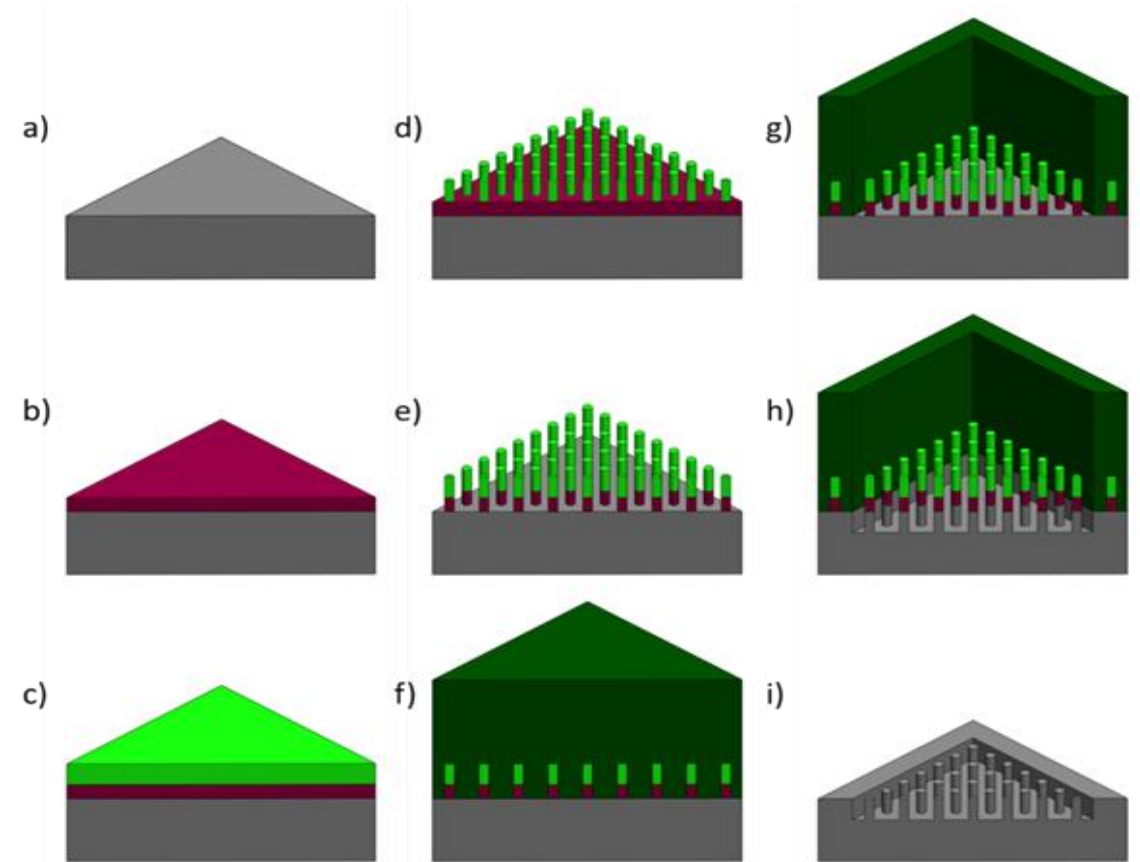
Legend

Silicon

BARC

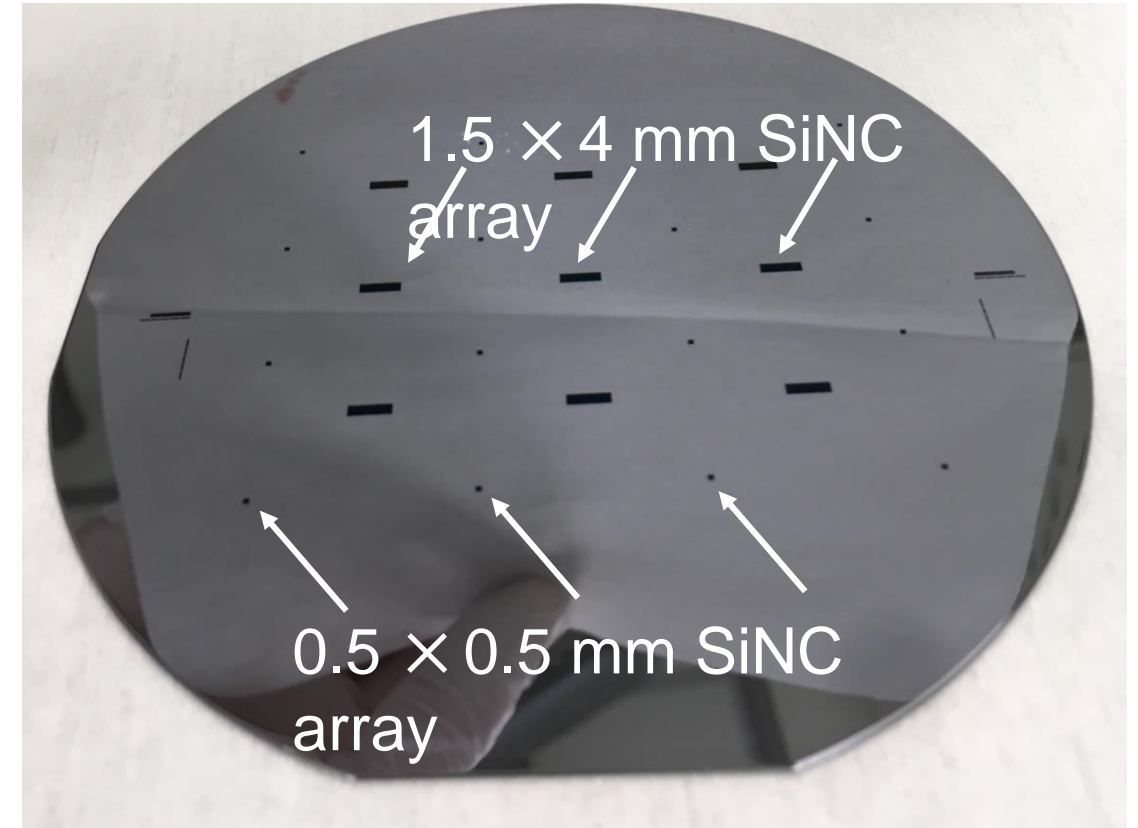
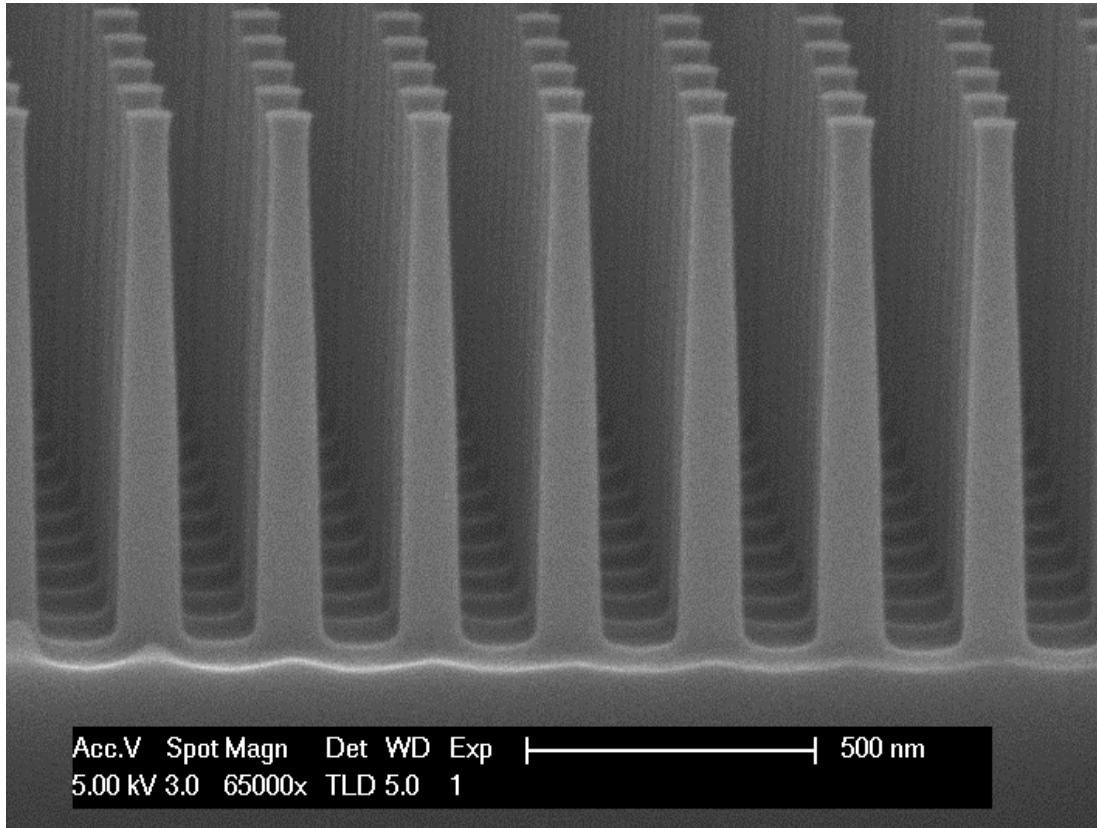
PFI 88A

OiR 907

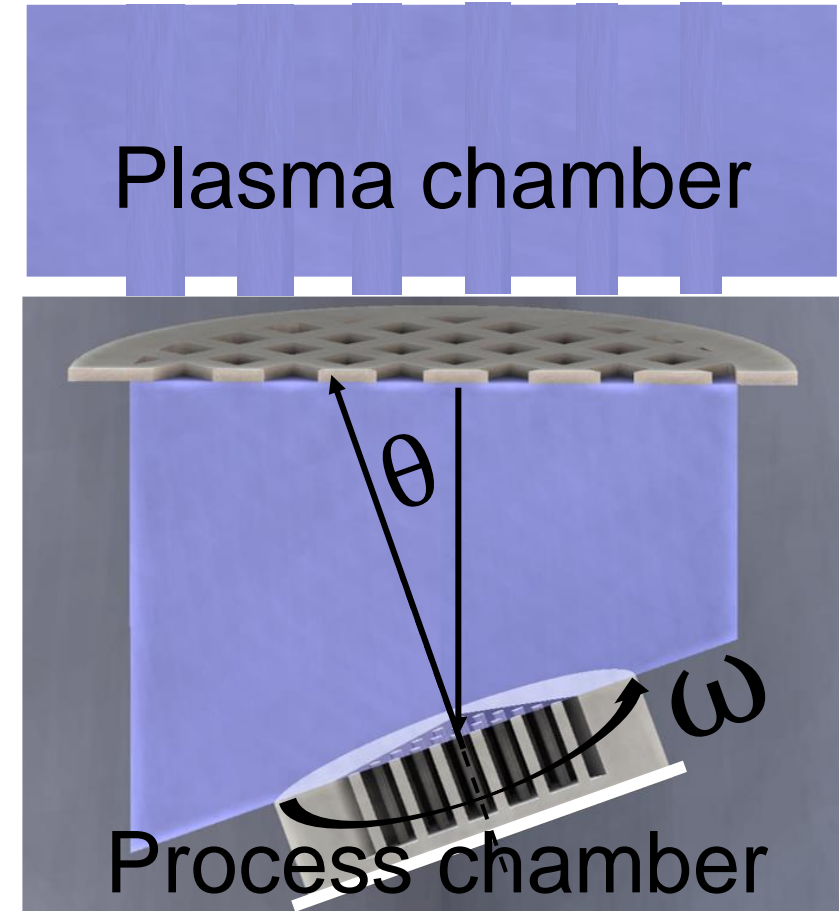
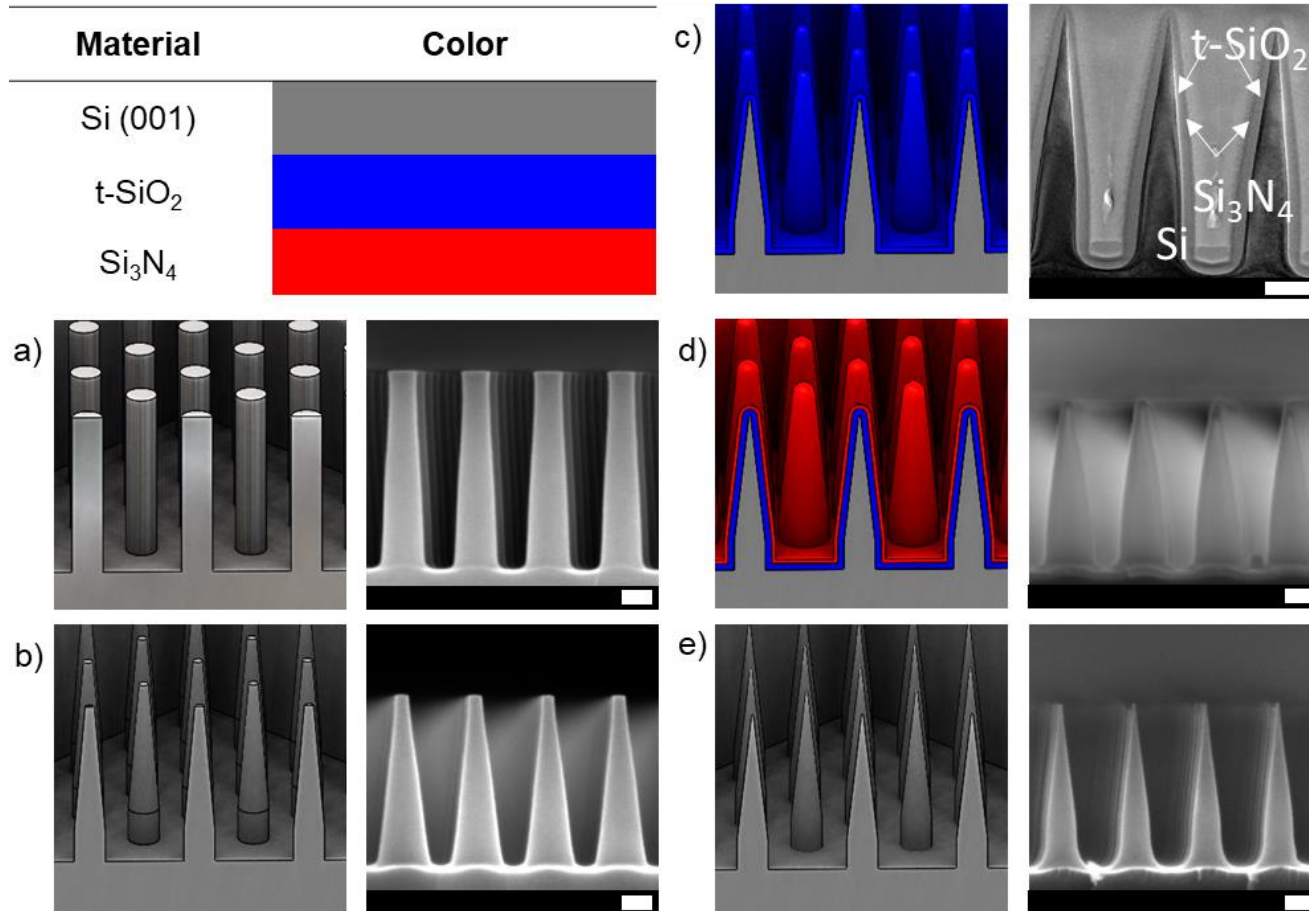


D. Jonker et al. 'Wafer-scale fabrication and modification of silicon nano-pillar arrays for nanoelectronics, nanofluidics and beyond' Int. J. of Nanotechnology (2020)

General process flow: reactive ion etching of silicon

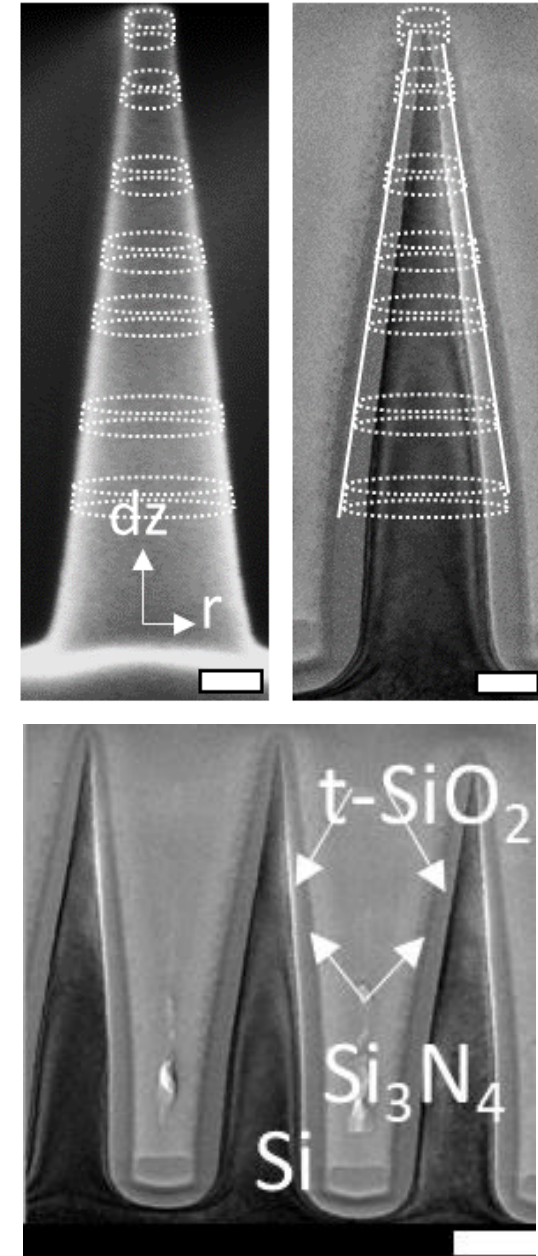


Fabrication of silicon nanocones



Tapered Oxide thickness

- Gradient oxide thickness along the cone slant
- Oxide thickness ~ 20 nm at the bottom and ~ 5 nm at the apices.

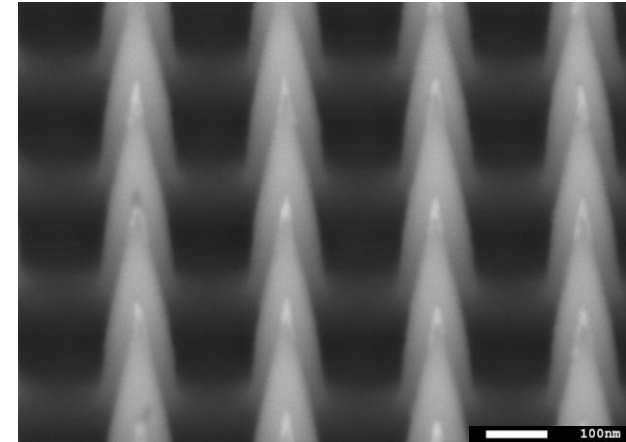


Formation of PtSi on Silicon Nanocones

1. Silicon nanocones with silicon dioxide



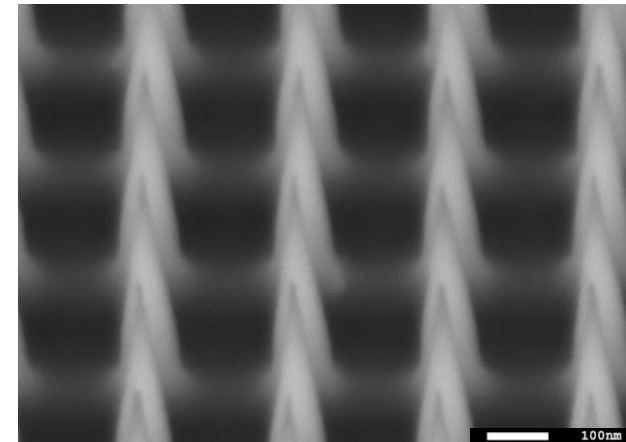
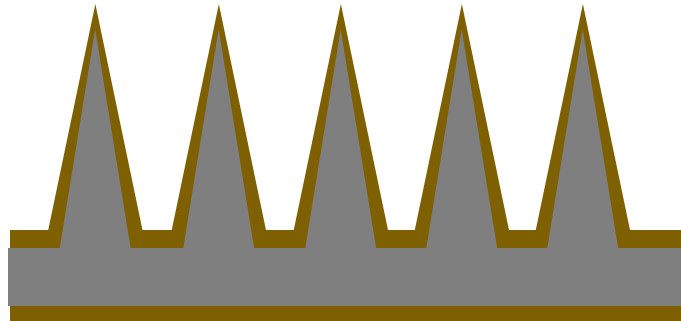
2. Etching of silicon dioxide



3. Sputter deposition of Platinum

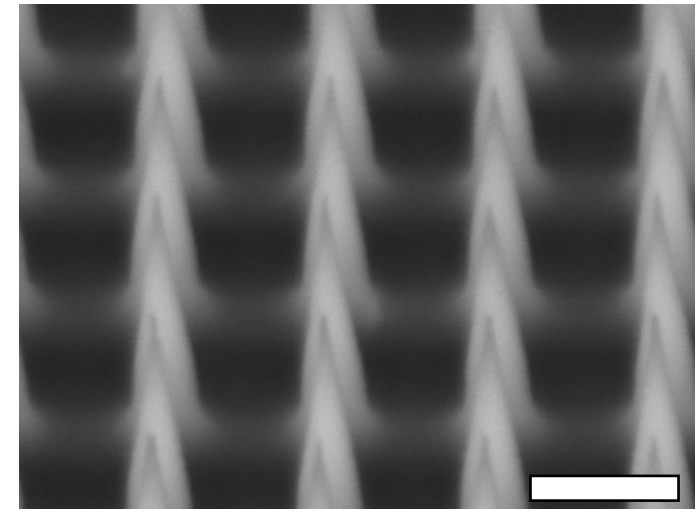
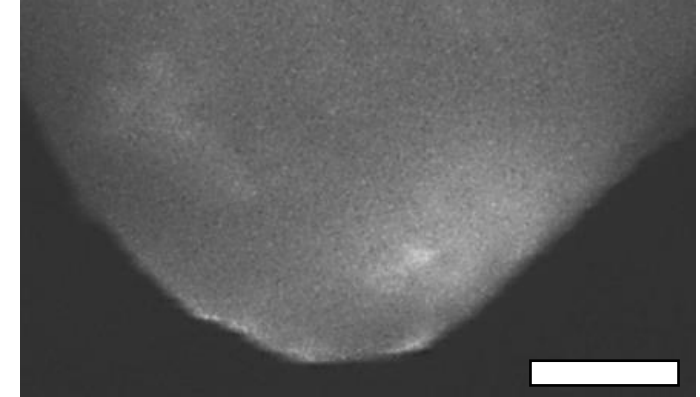
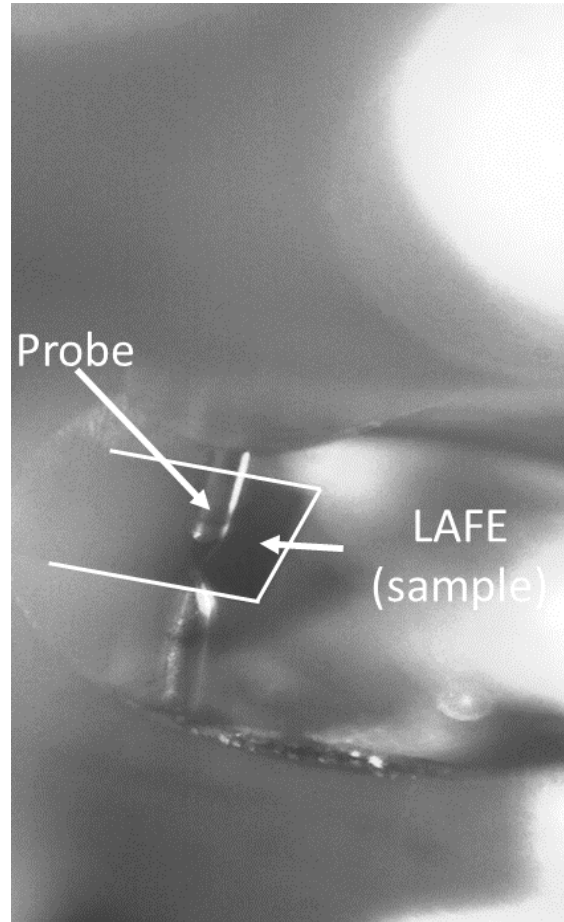
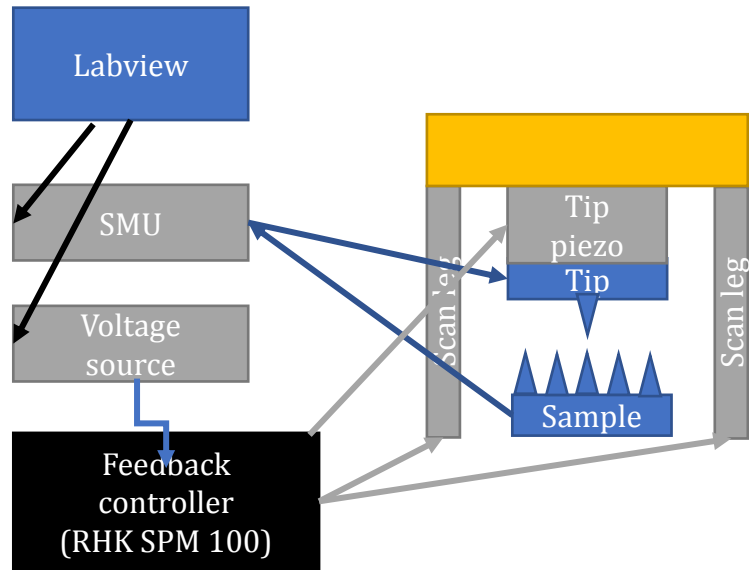


4. Rapid thermal annealing forming Platinum Silicide



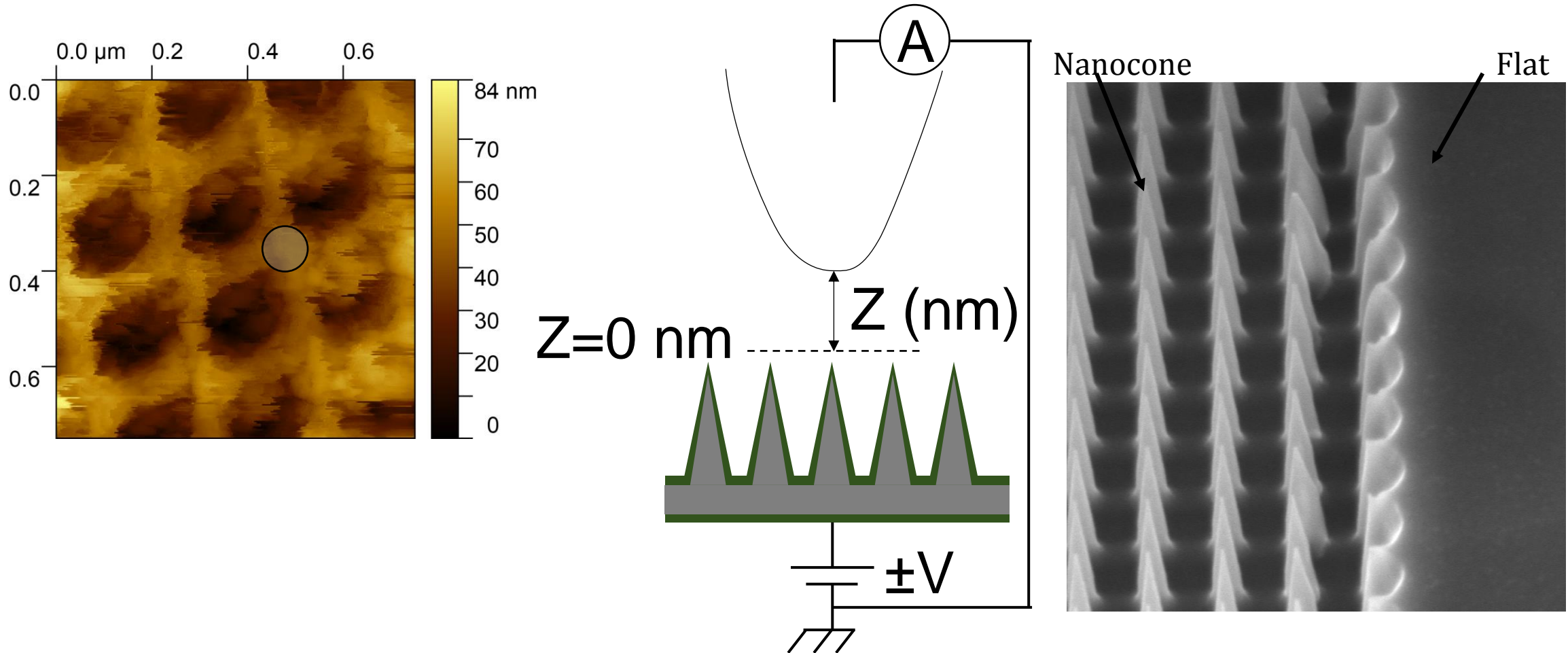
Experimental Setup

Scanning tunneling microscope (Probe)



Discrete Z, I(V)-Spectroscopy

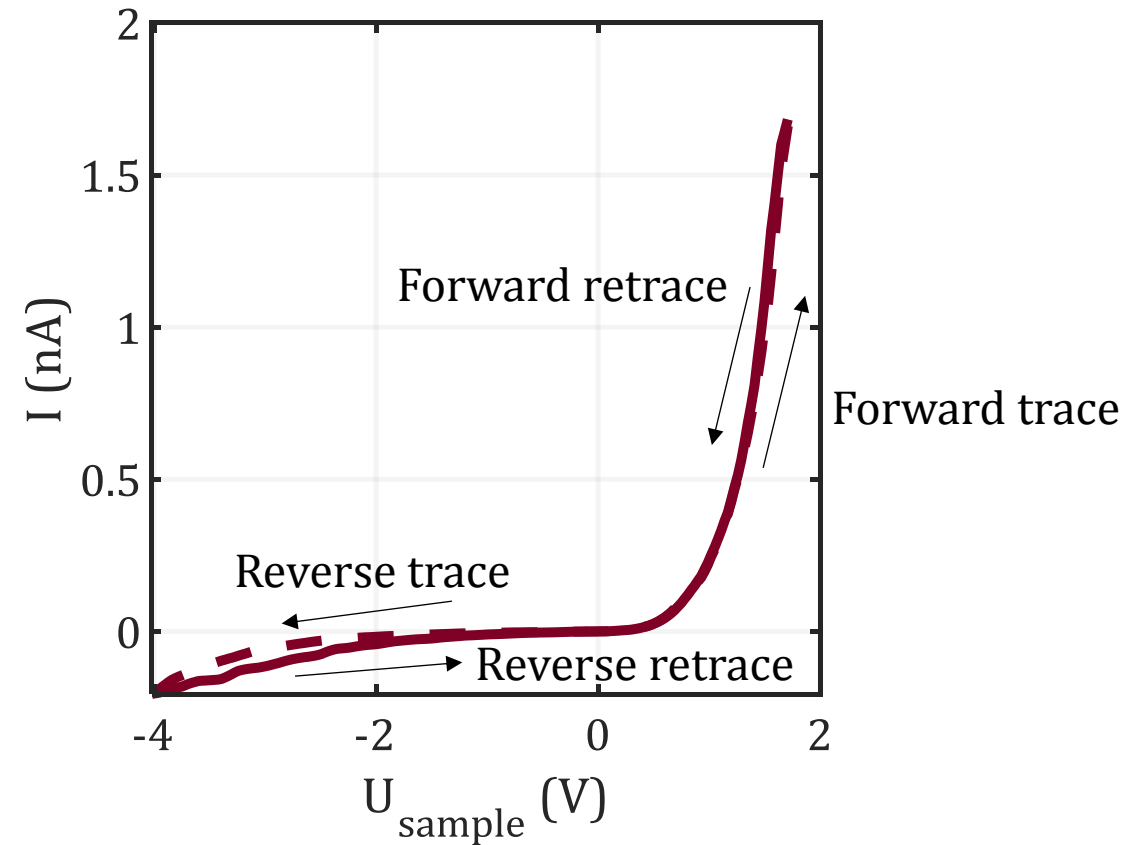
Si
PtSi



Some background

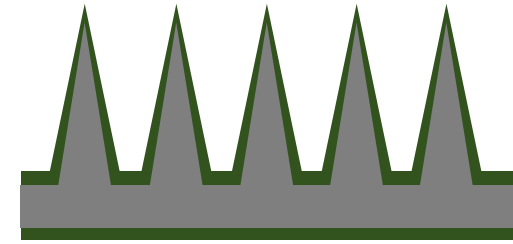
Measurement Conditions

- Approach at $\pm V_{\text{app}}$ applied to sample (probe grounded)
- Approach current (closed loop)
 $I_{\text{app}} = 1 \text{ nA}$
- $Z_{\text{app}} \equiv 0 \text{ nm}$
- Switch off feedback (open loop)
- Record I as function of V_{app}
- V_{set} is either a preset value or a potential at which a limiting current is reached (in the image $V_{\text{set}} = \pm 2 \text{ V}$ or V_{lim} for $I_{\text{lim}} = 1.8 \text{ nA}$)

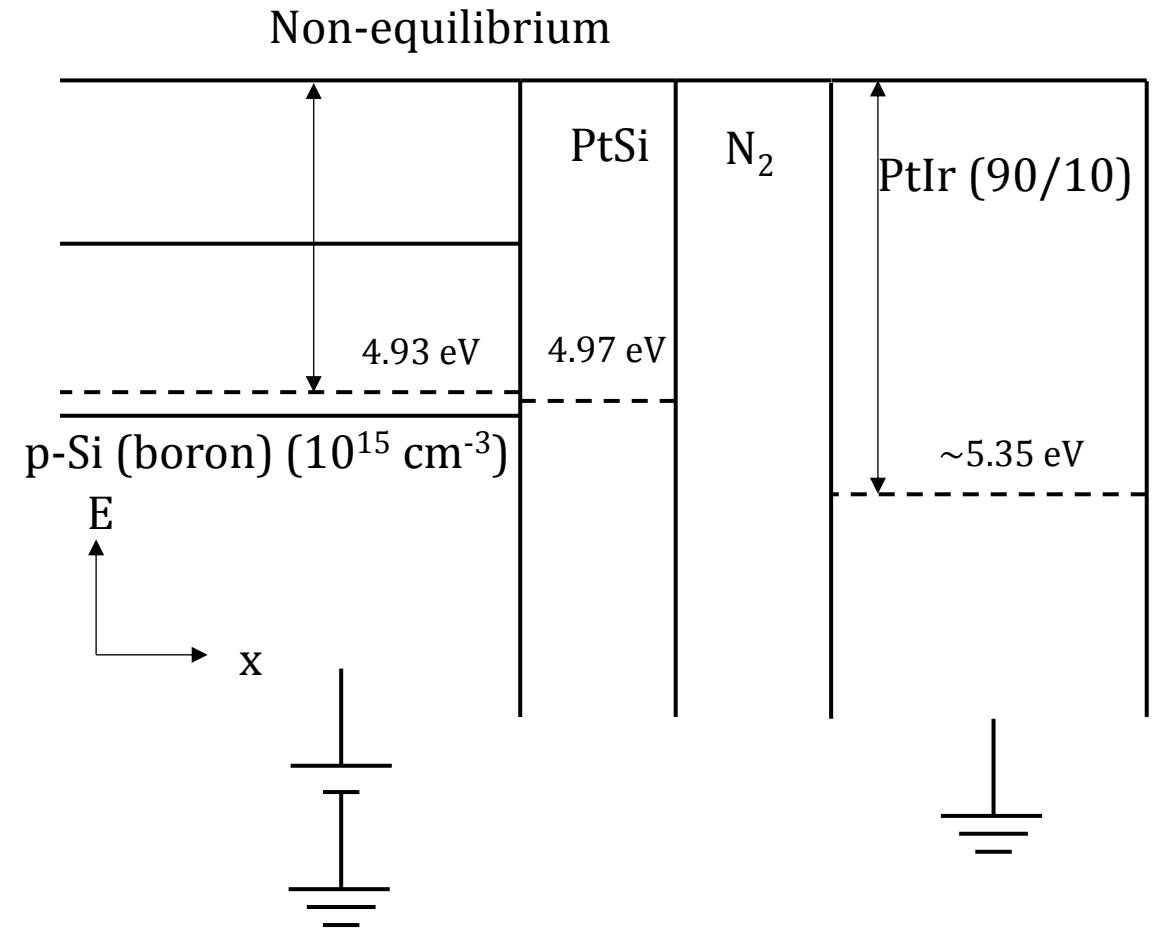
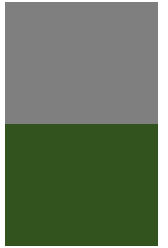


Band Diagram

- $E_{f,Si} = \chi + E_G - \frac{k_b T}{q_e} * \ln \left(\frac{N_A}{N_V} \right)$
- PtSi (211);(110) (platinum rich ; platinum poor) PtSi formation
- $\Phi_{PtSi} = 4.97 \text{ eV}$
- $\Phi_{PtIr} = 5.35 \text{ eV}$



Si
PtSi

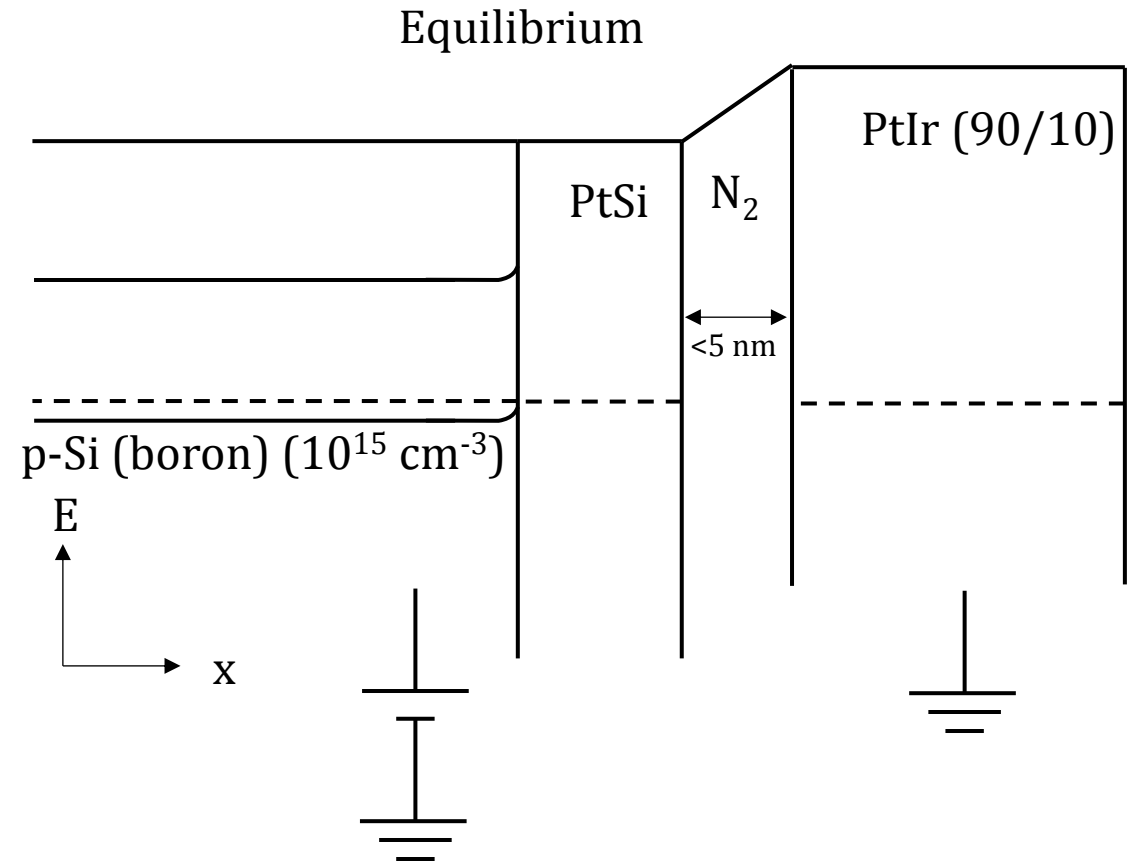


Manish K. Niranjana *et al.* 'Theoretical investigation of PtSi surface energies and work functions' Phys. Rev. B. (2006)

Band Diagram

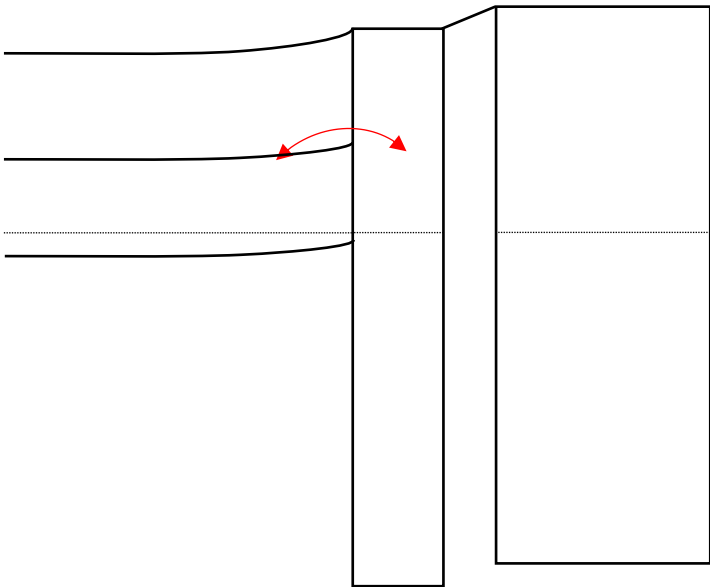
1. $E_{f,Si} = \Phi_{PtSi}$
2. $\Phi_{PtSi} = \Phi_{PtIr}$

The p-type silicon equilibrates with the PtSi, where the metallic PtSi equilibrates with the PtIr probe.



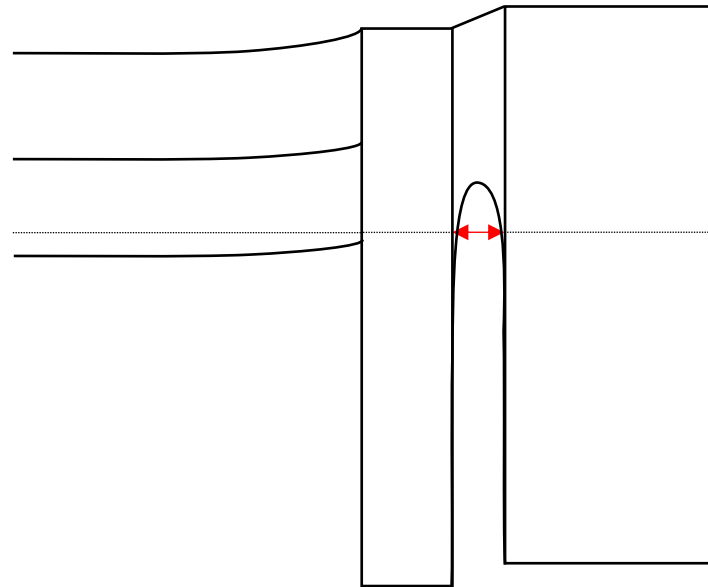
Different Barrier models

Thermionic Emission
(TE)



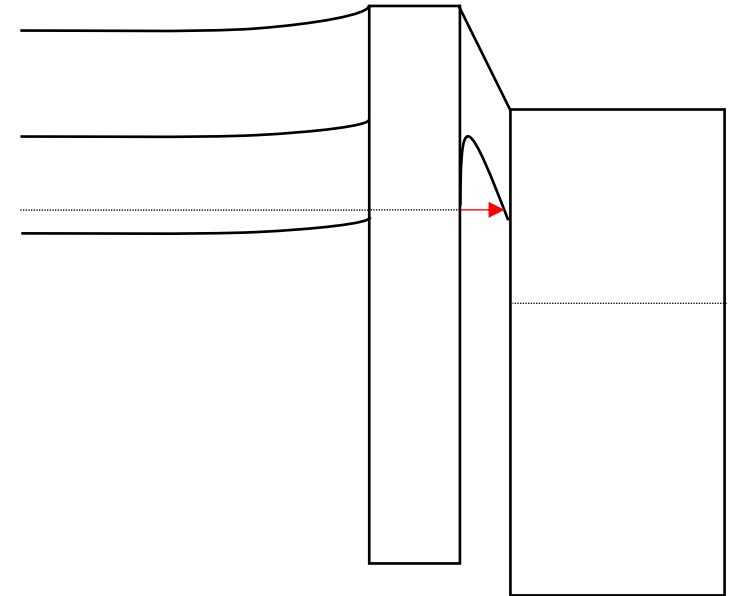
$$\log(I) \propto V$$

Direct Tunneling (DT)



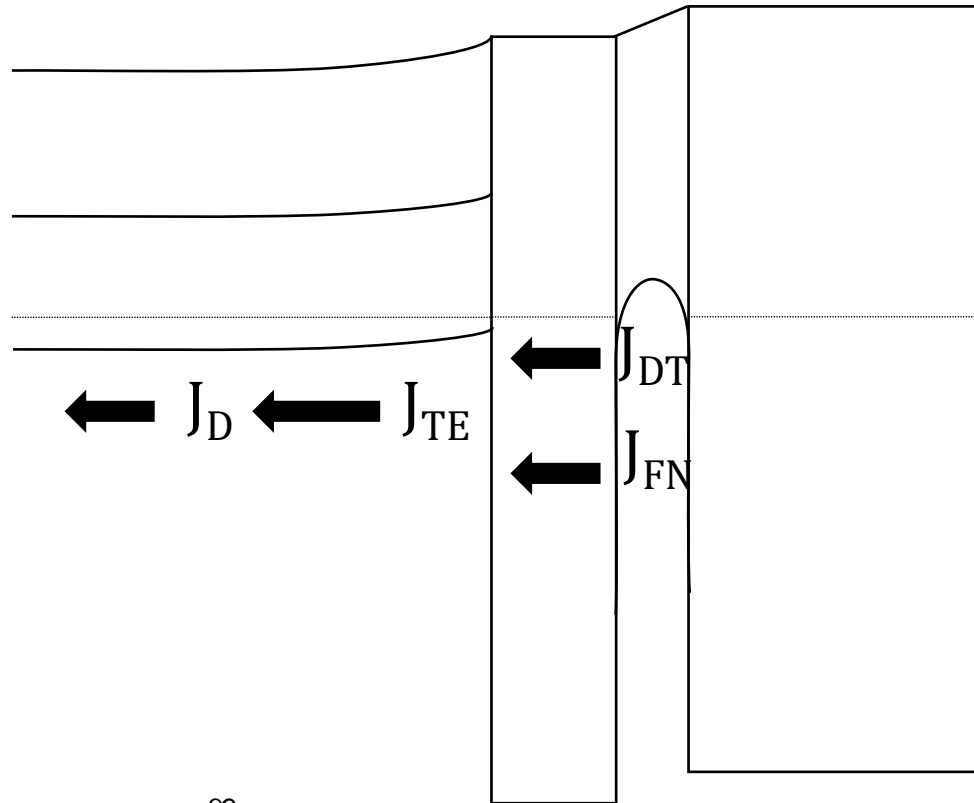
$$\log\left(\frac{I}{V^2}\right) \propto \log(1/V)$$

Field emission (FN)



$$\log\left(\frac{I}{V^2}\right) \propto \frac{1}{V}$$

Positive potential on Sample

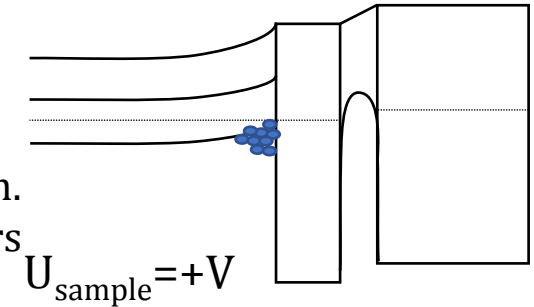


$$J = \int_{-\infty}^{\infty} q \cdot v_x \cdot D(E) dn$$

$$dn = N(E) \cdot F(E) \cdot dE$$

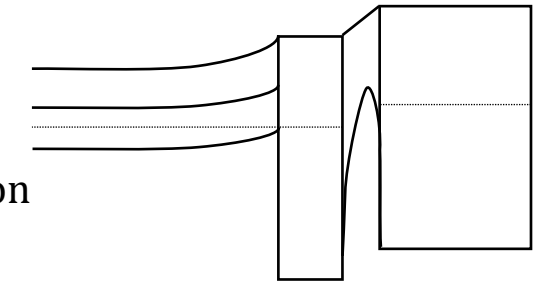
1. $J_{FN} < J_{DT} \ll J_D$

Build-up of potential
In space-charge region.
Potential at PtSi lowers



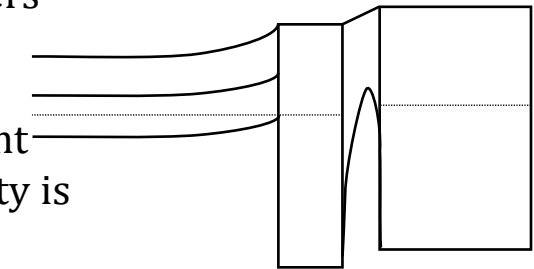
2. $J_{DT} < J_{FN} \ll J_D$

Build-up of potential
In space-charge region
slows down.
Potential at PtSi lowers



3. $J_{FN} \geq J_D$

Barrier is non-existent
(Tunneling probability is
Unity). Current is
controlled by Drift-
Diffusion.



Negative potential sample

1. $J_{FN} < J_{DT} \ll J_D$

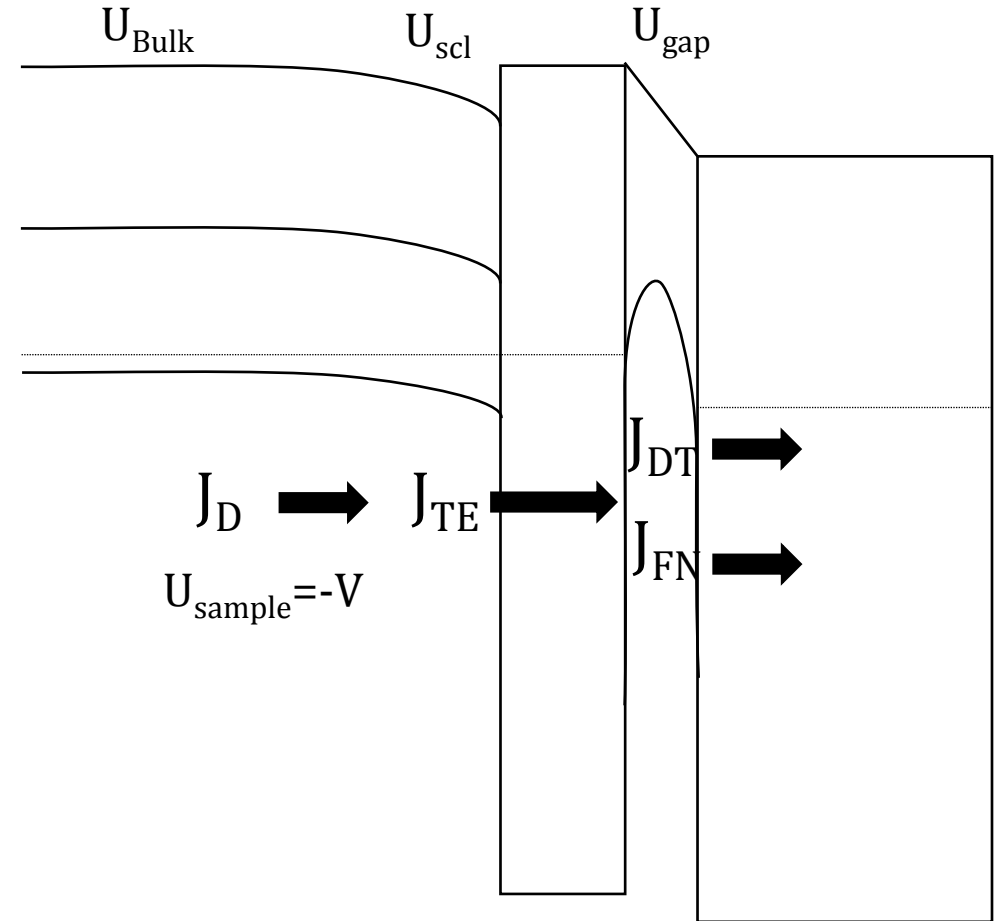
Build-up of potential in space-charge region.

Potential at PtSi increases.

2. $U_{\text{sample}} = U_{\text{Bulk}} + U_{\text{scl}} + U_{\text{gap}}$

Depletion of holes and build-up of electrons

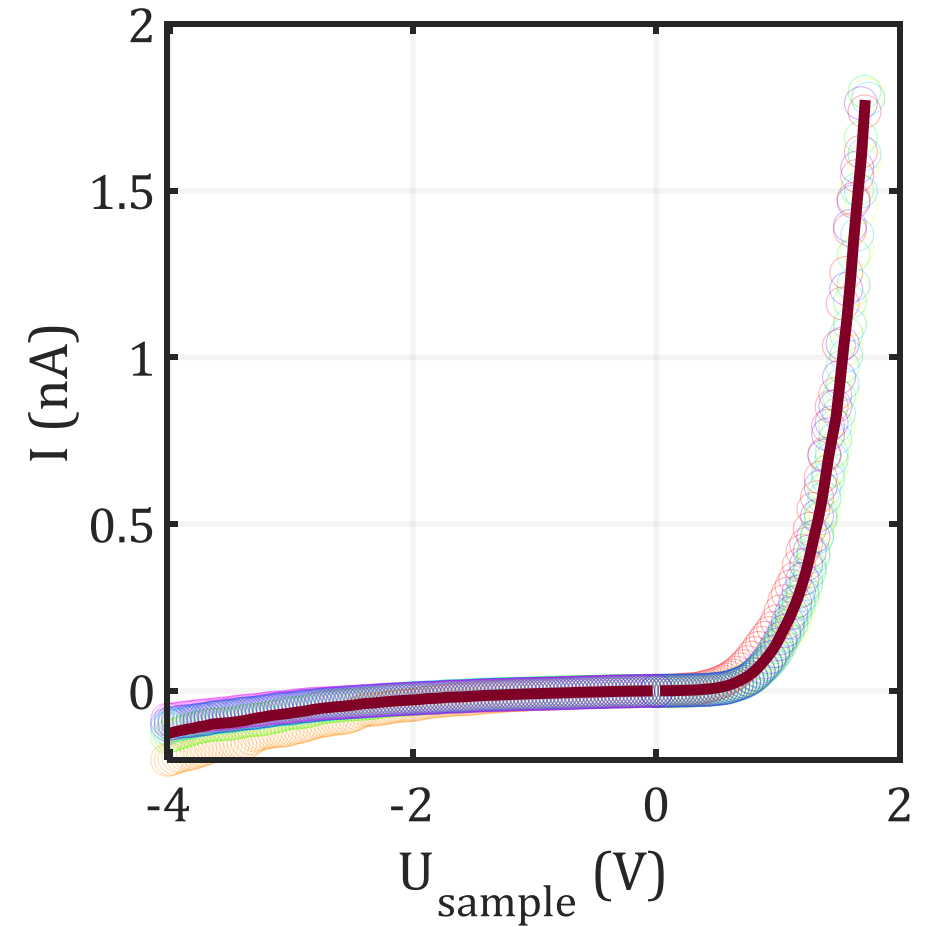
At the p-Si PtSi interface (Field penetration)



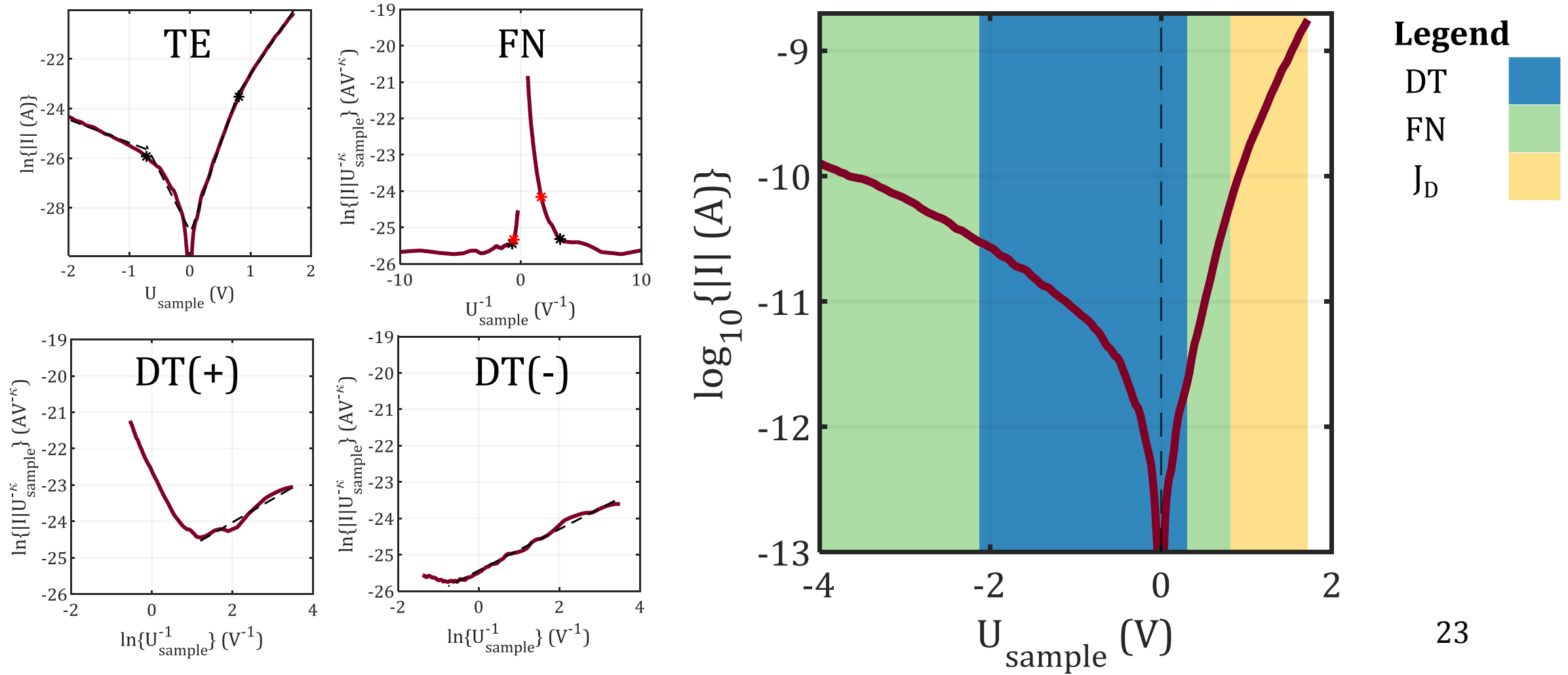
Results

Measurement over flat surface

- Average of 5 measurements over flat surface.
- $U_{\text{lim}} = \pm 4 \text{ V}$
- $I_{\text{lim}} = 1.8 \text{ nA}$

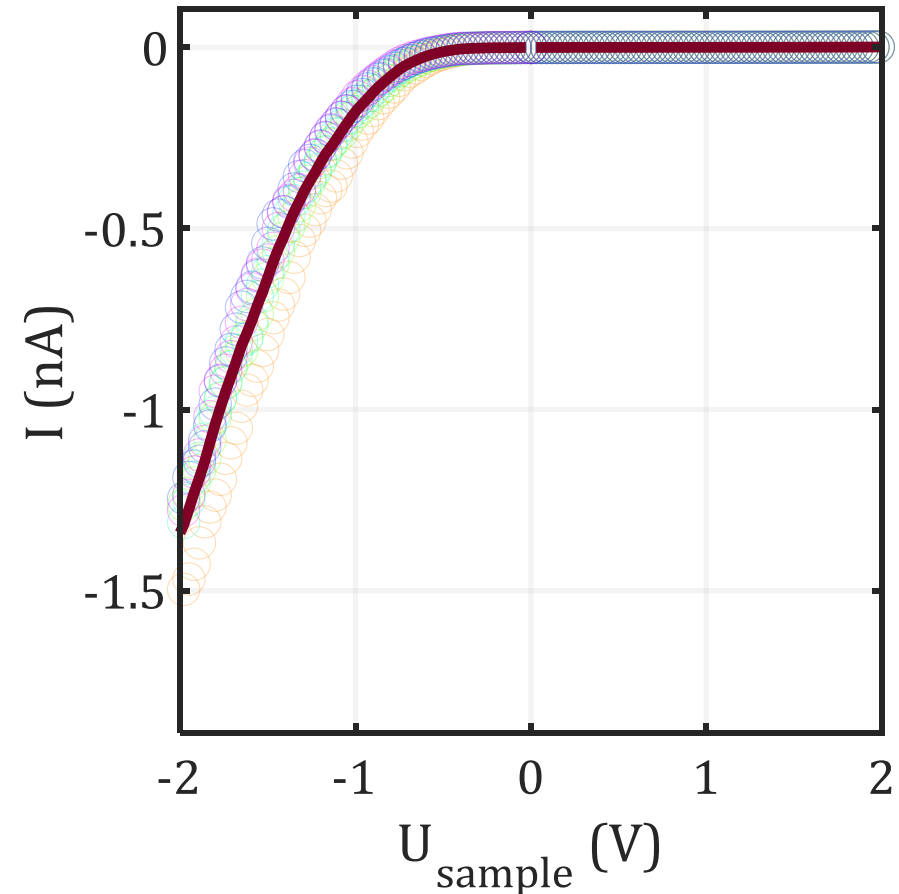


Applying different Barrier models

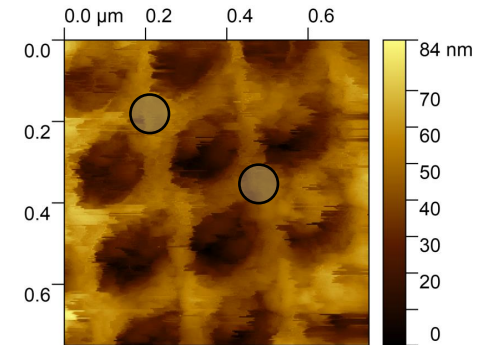
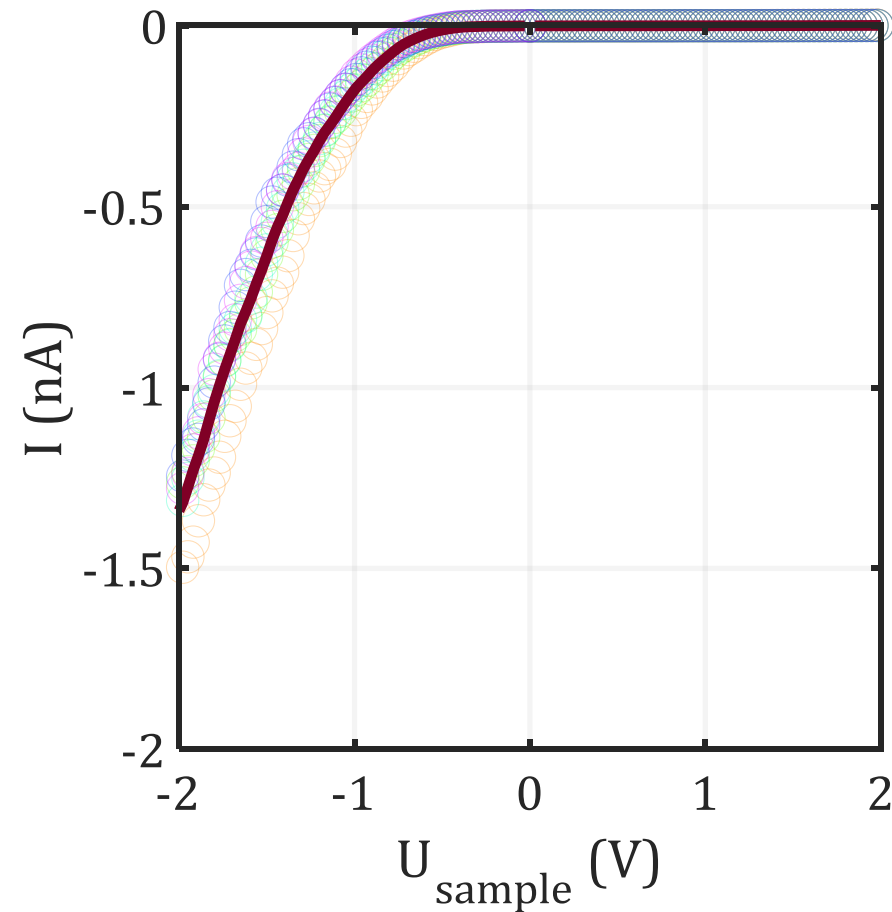
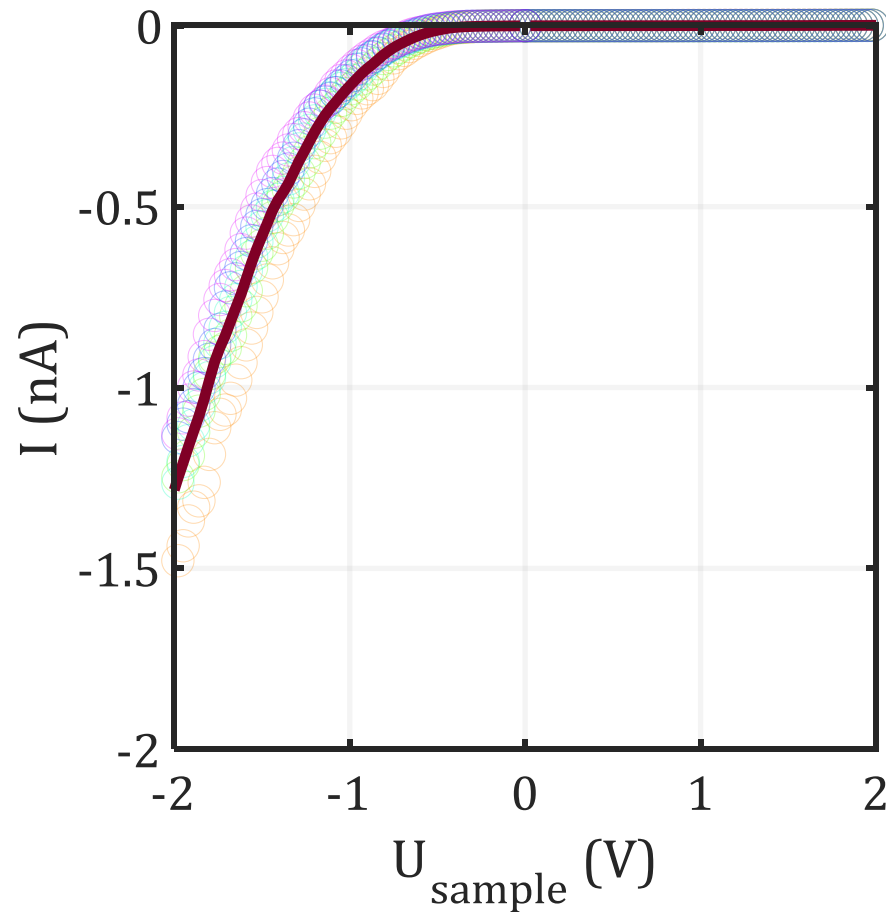


Measurement over Cone

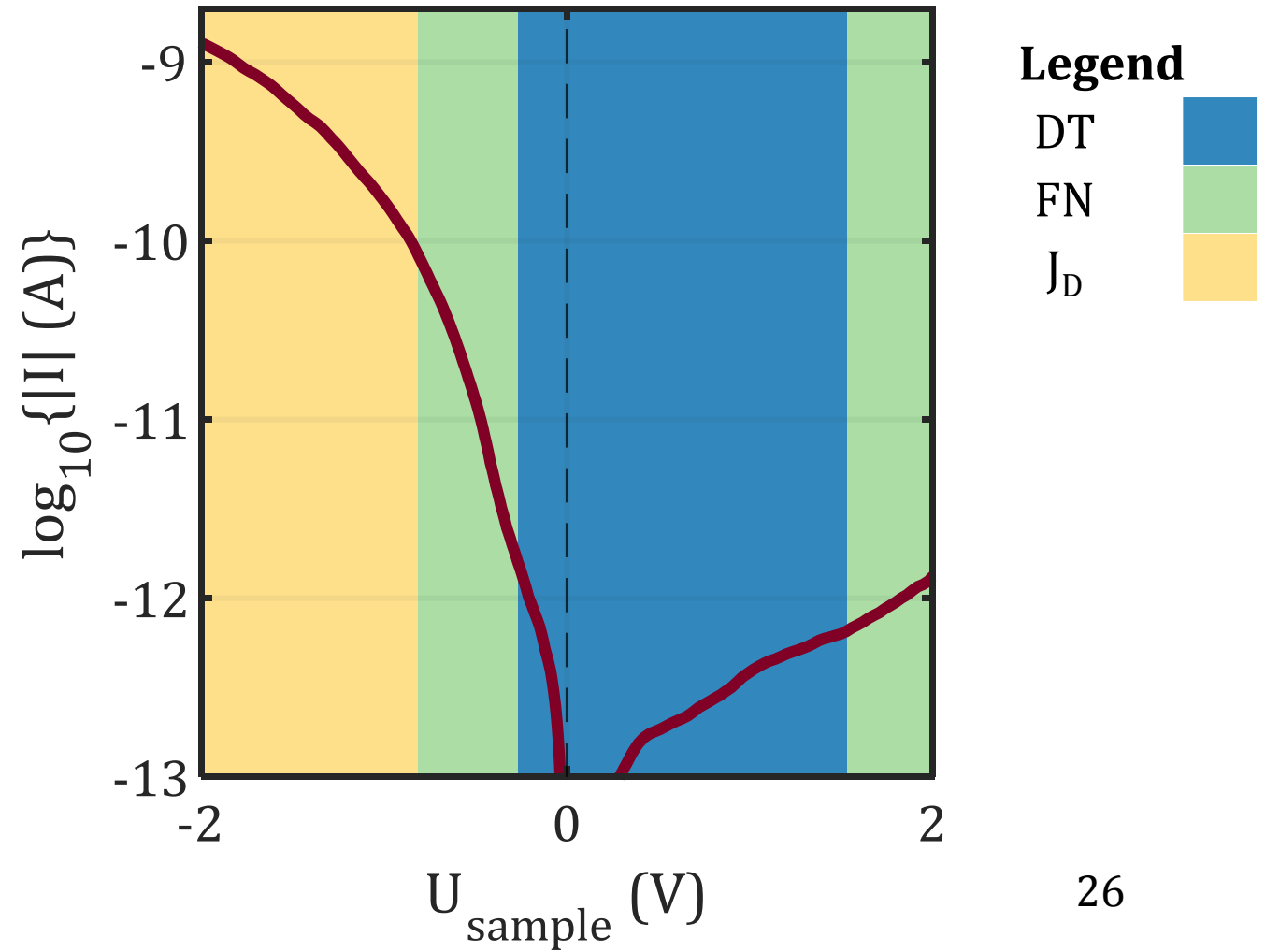
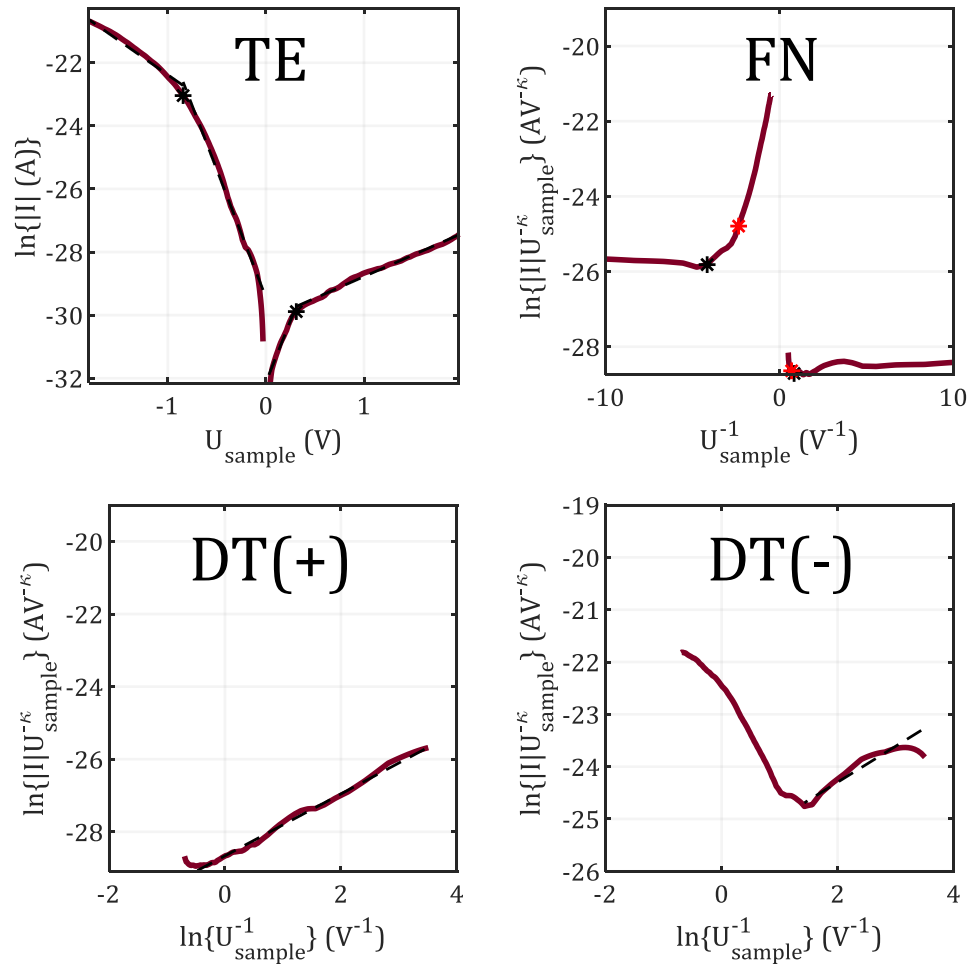
- Average of 5 measurements over conical surface.
- $U_{\text{lim}} = \pm 2 \text{ V}$
- $I_{\text{lim}} = 1.8 \text{ nA}$



Measurement over two different cones

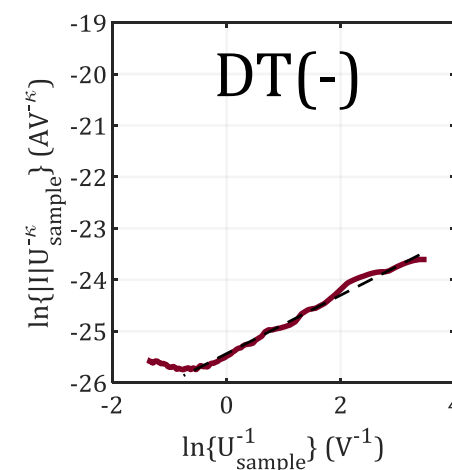
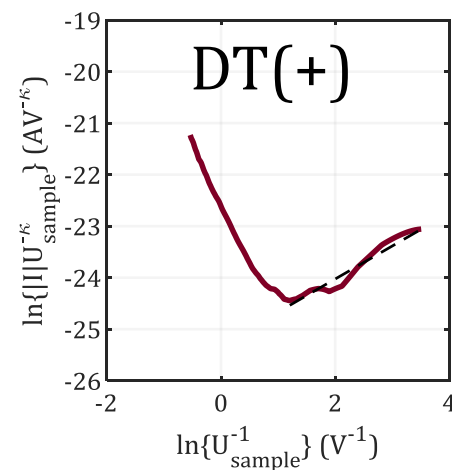
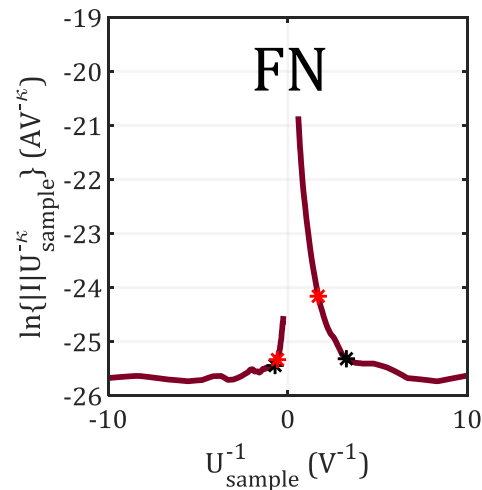
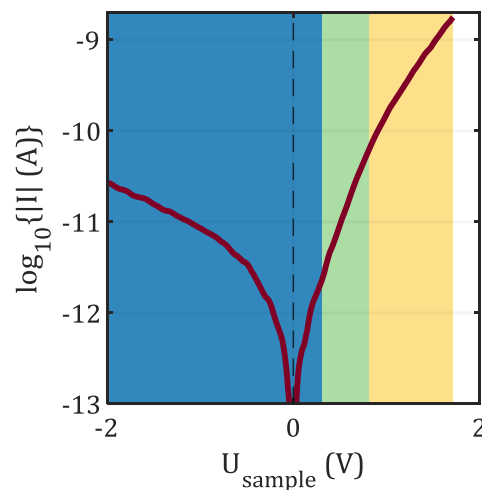


Again: Applying different Barrier models

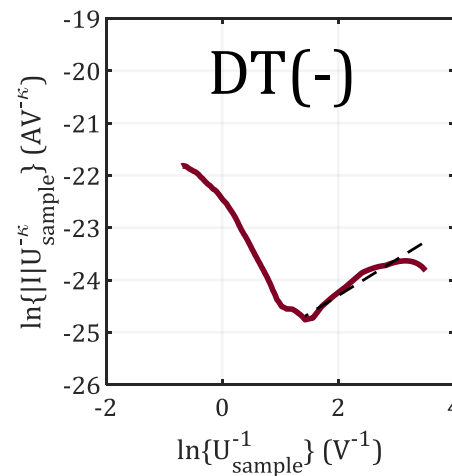
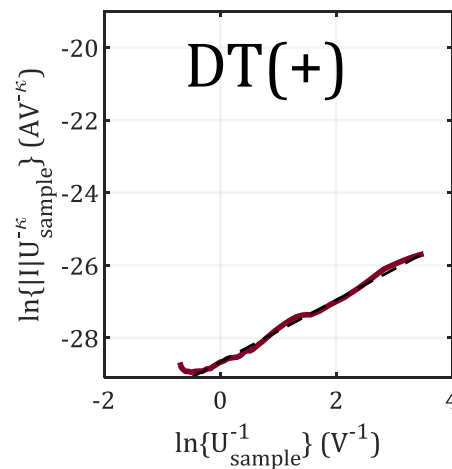
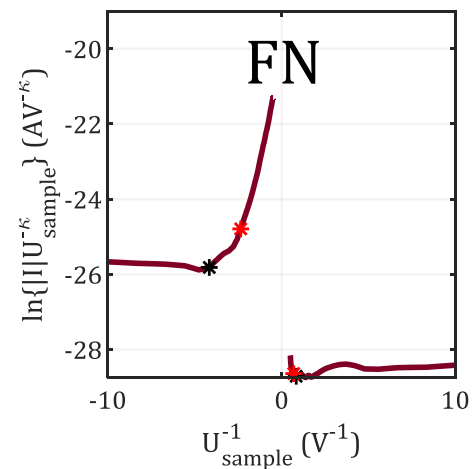
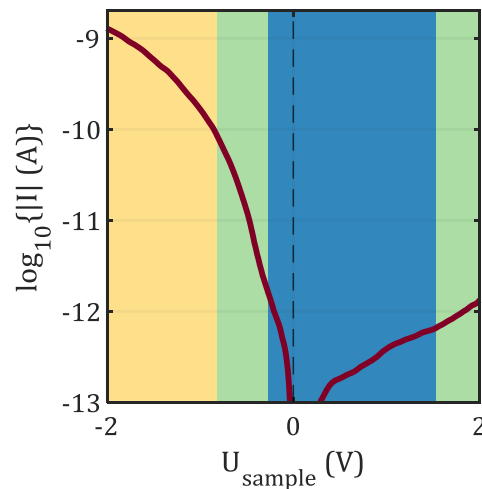


Comparison of flat and cone

Flat

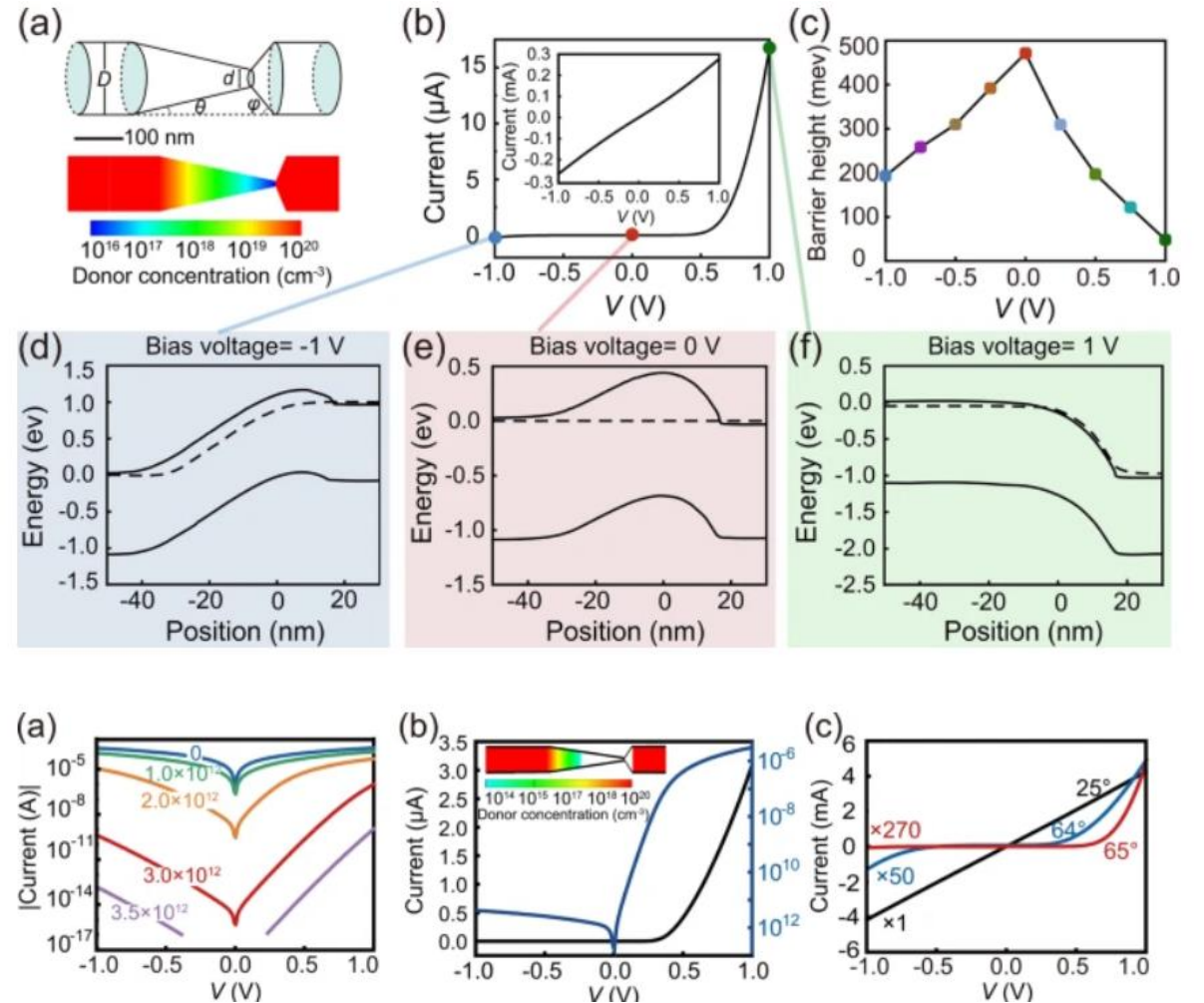


Cone



A Geometric diode

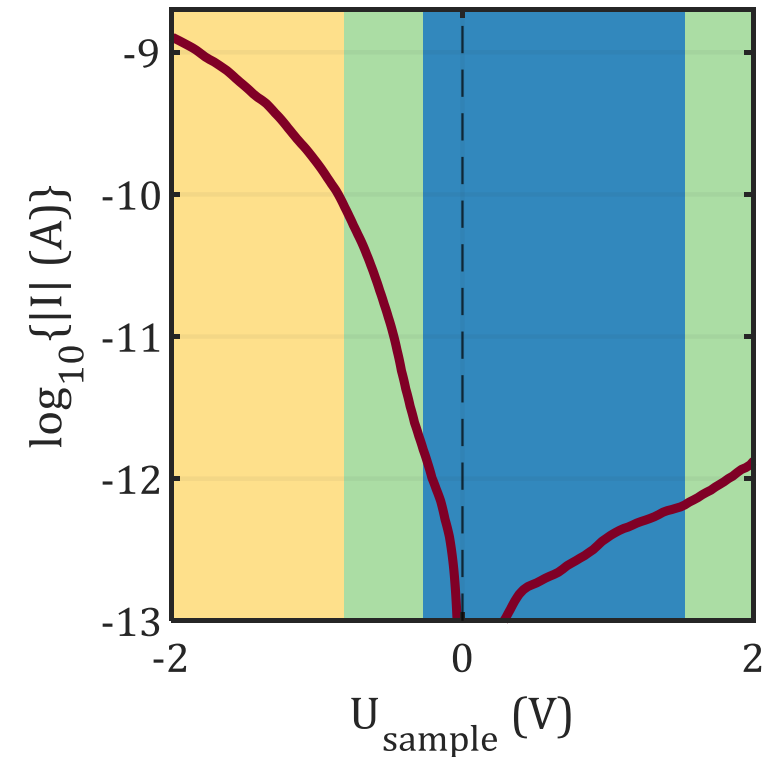
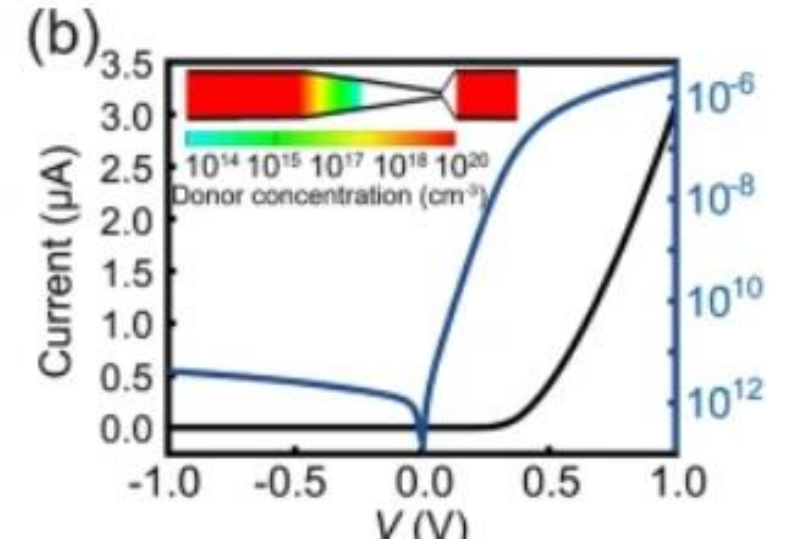
- Key factors:
 - surface states
 - Geometry
 - surface passivation



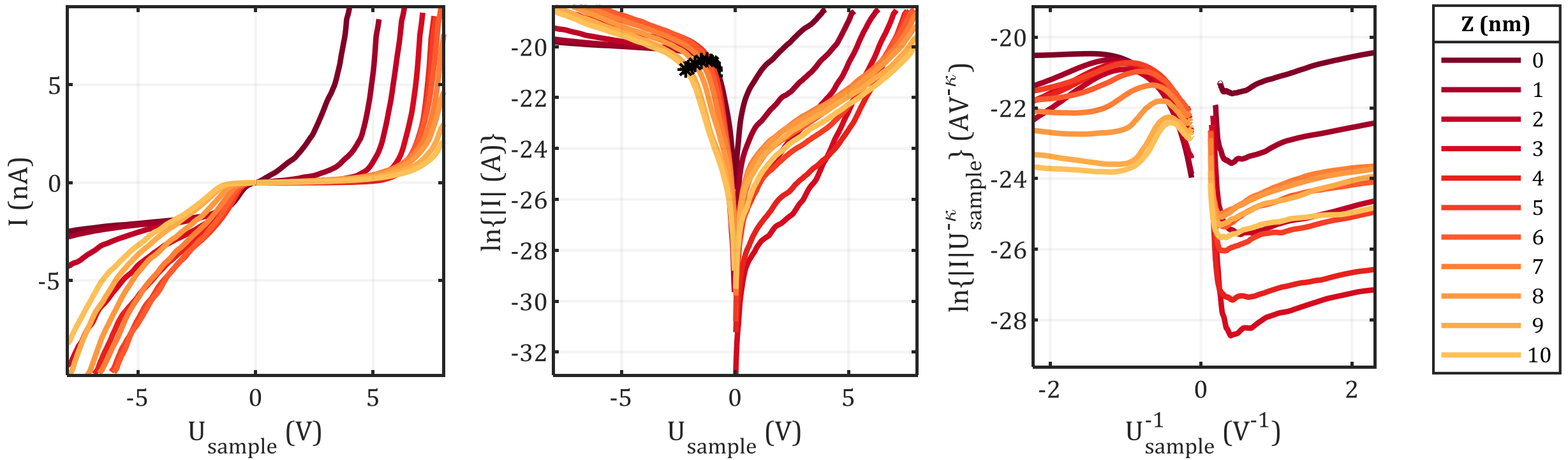
M. Baiet al. 'Asymmetric bias-induced barrier lowering as an alternative origin of current rectification in geometric diodes' Nat. Com.PhysB. (2021)

Summarizing

- PtSi coated p-Si nanocone arrays are inherently transport limited devices
- Effect of PtSi is yielding an n-type current voltage behavior possibly due to surface states, and pinning effects.

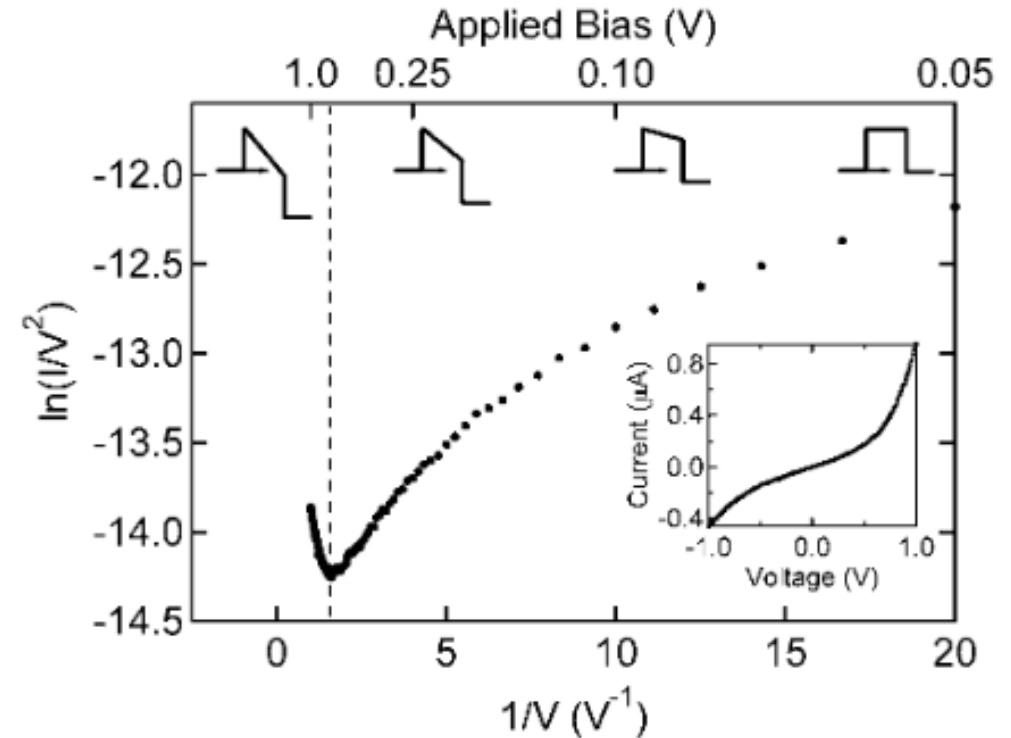


Moving away from the substrate



The transition Voltage

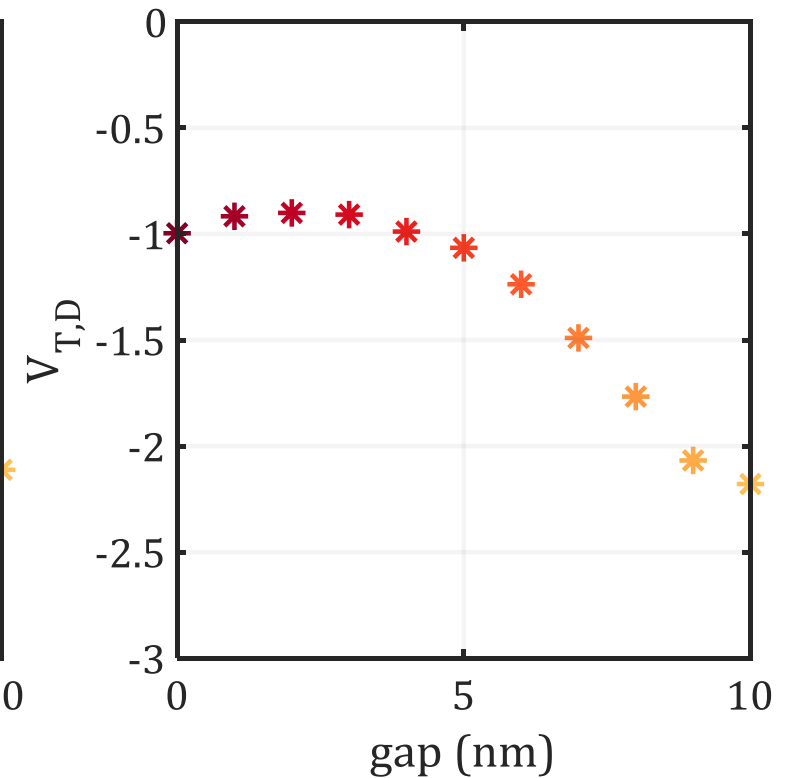
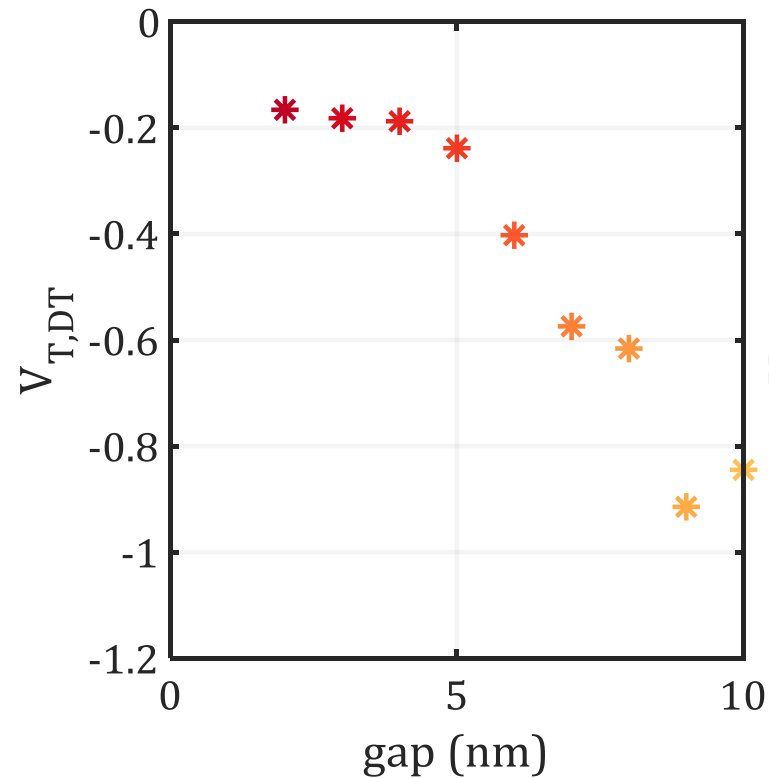
- Transition Voltage determines the Crossover point from DT to FN regime
- Furthermore, we can consider the knee voltage at which the Current is substrate limited



Jeremy M. Beebe *et al.* 'Transition from Direct Tunneling to Field Emission in Metal-Molecule-Metal Junctions.' *Phys. Rev. Lett.* (2006)

Transition voltage

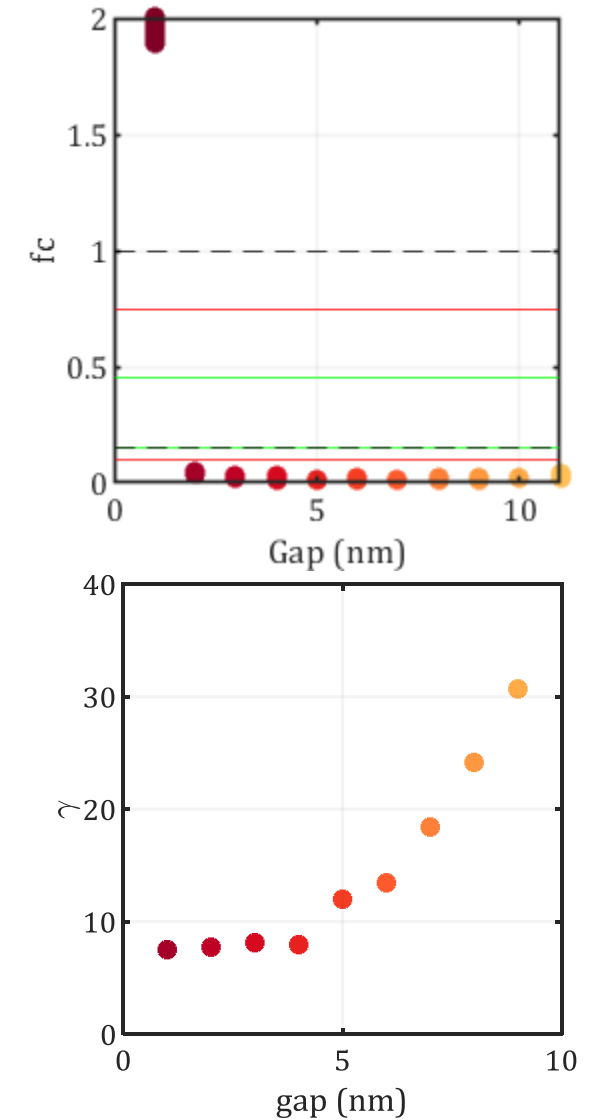
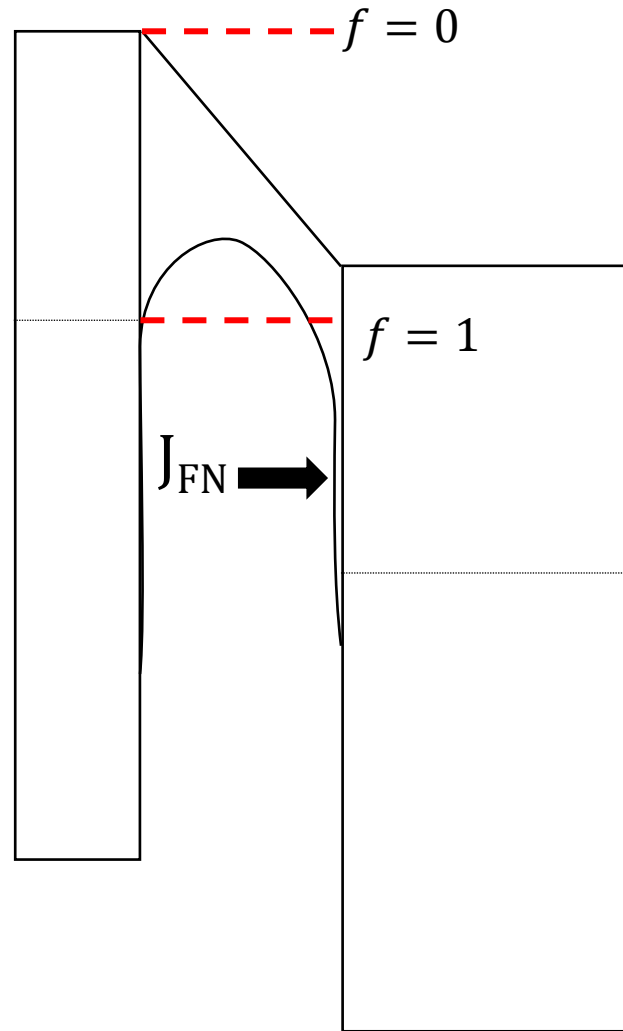
- Since the increase in gap is 10 nm, why $V_{T,DT}$ only moves by 1V or so
- Remarkable correlation between DT-FN regime change and Substrate limited current.
- Field emission eventually becomes substrate limited



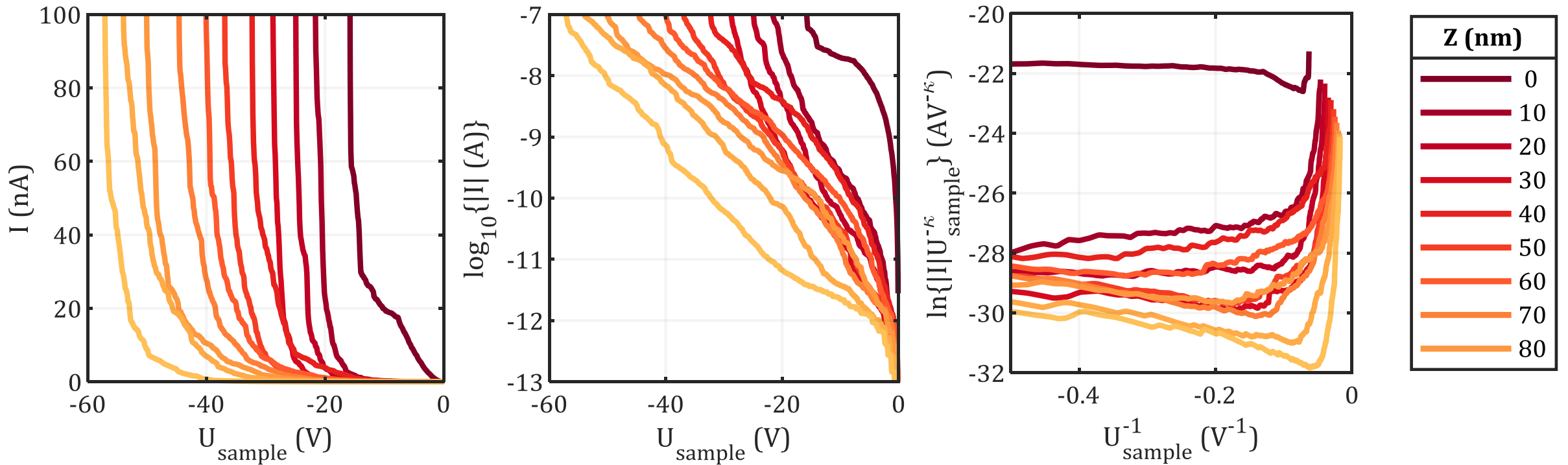
How to explain

- $J = \int_{E_c}^{\infty} q \cdot v_x \cdot D(E) dn$
- $dn = N(E) \cdot F(E) \cdot dE$
- What about the barrier transparency (E-Field)

- $f = \frac{F_L}{F_R}$
- $\gamma = \frac{gap}{\zeta_{ex}}$
- $\zeta_{ex} = \frac{S_{fit, MG}}{b_{FN} \cdot \Phi_{PtSi}^{\frac{3}{2}}}$

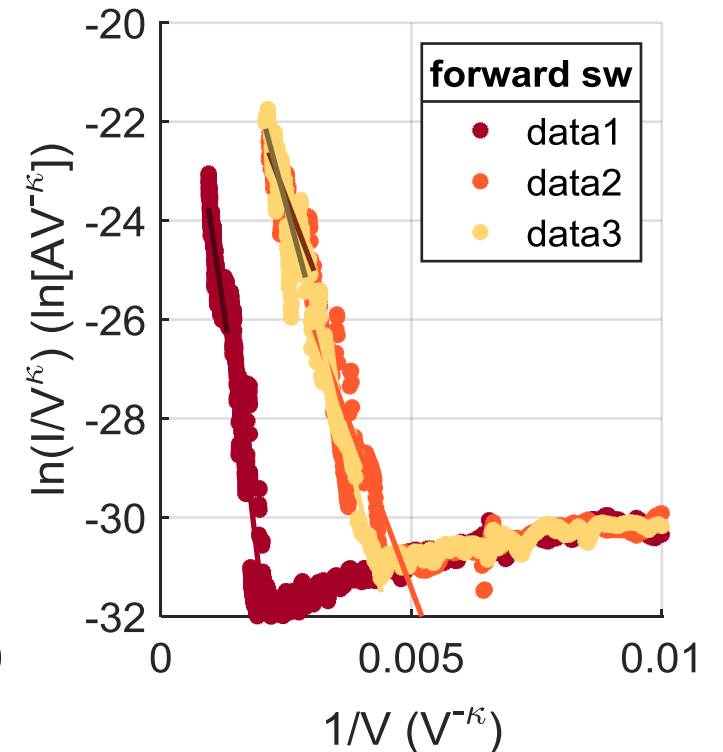
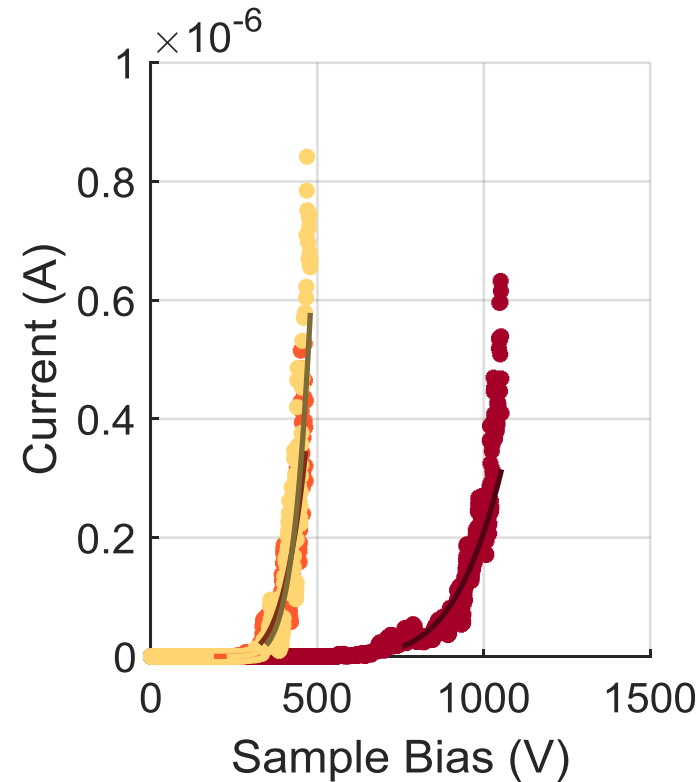
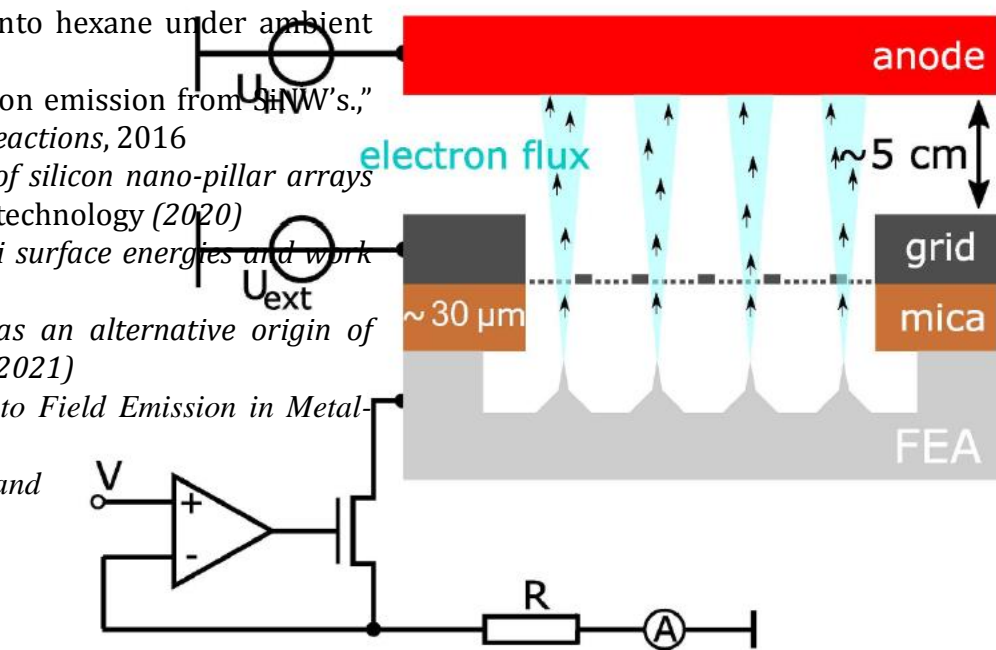


Even larger gaps



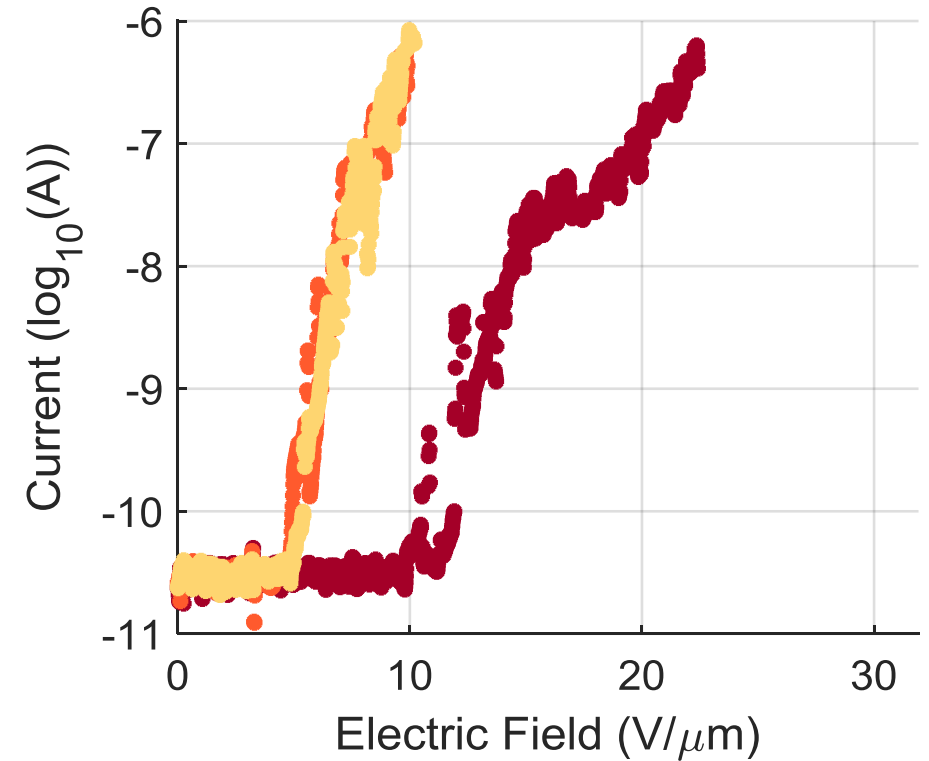
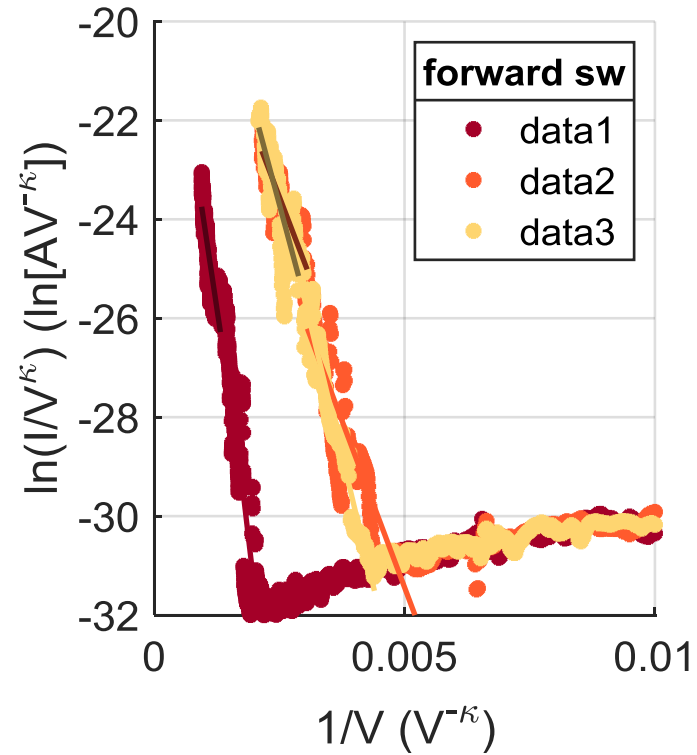
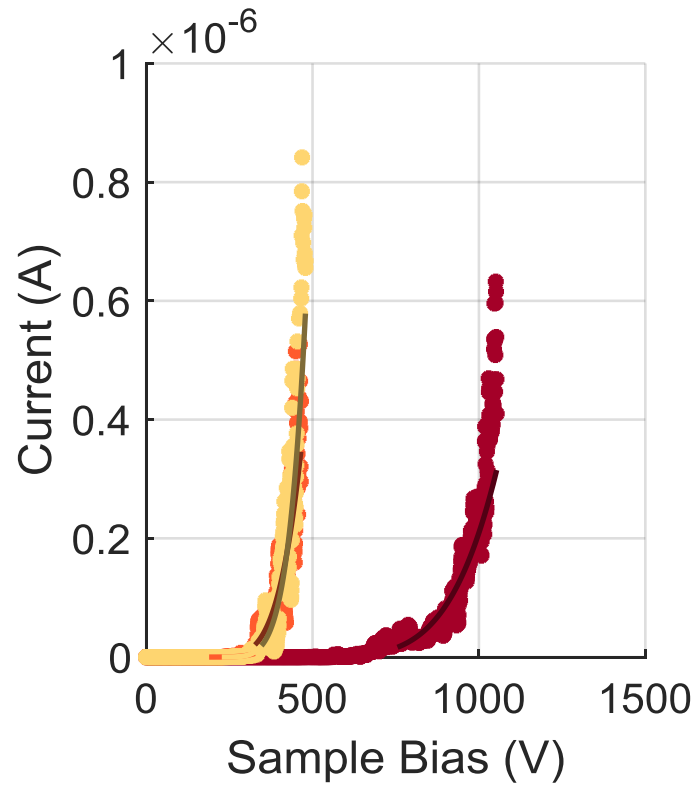
Same argument holds: Tunneling Barrier vs. Substrate limited current → Relate to mr. Edler

Large gap measurements

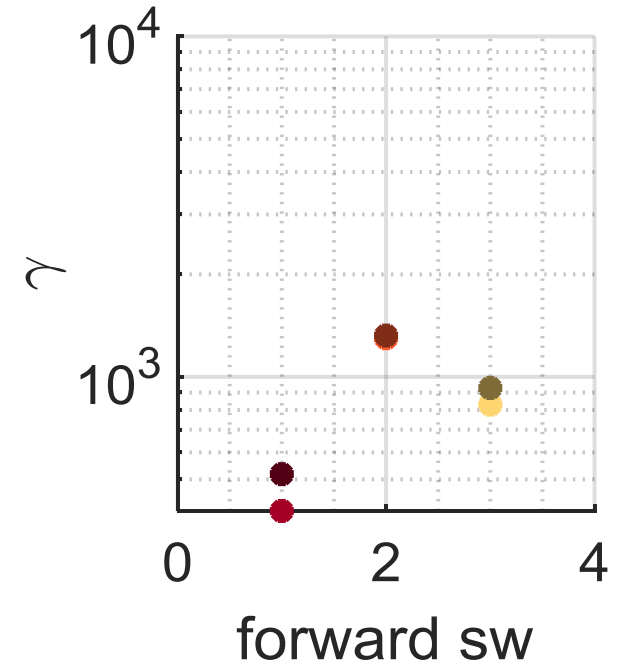
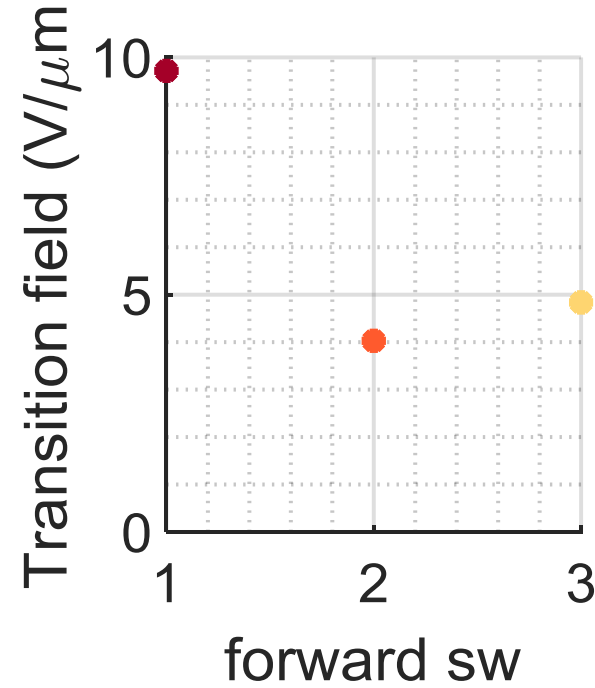
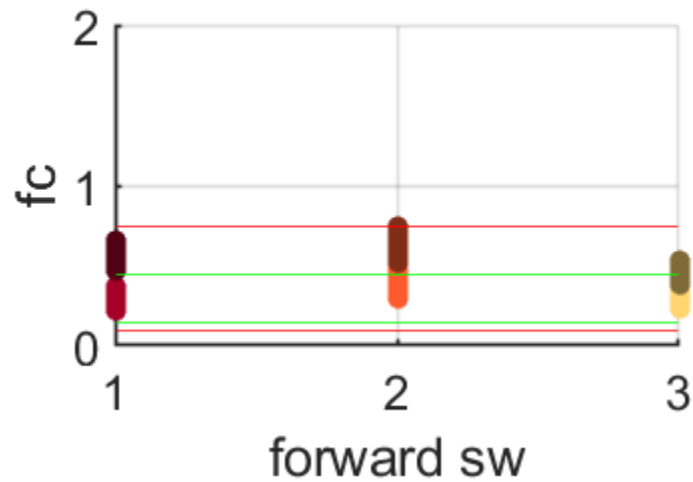


S, Edler et al. 'Silicon field emitters fabricated by dicing-saw and wet-chemical-etching'. J. Vac. Sci. Technol. B(2021)

Barrier models

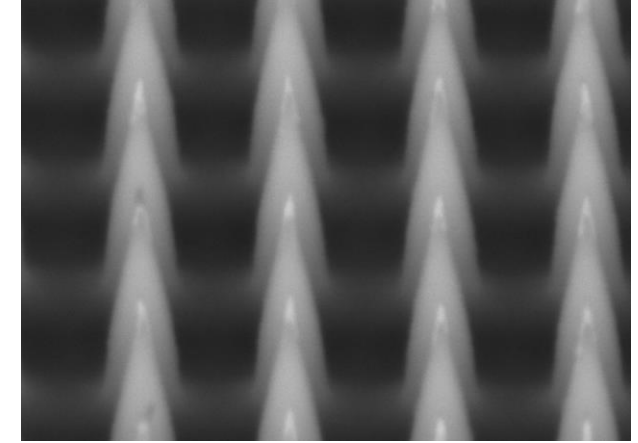


Field emission properties



Conclusion

- Presented a way to obtain highly homogeneous silicon field emitter array
- Possibility to (locally) silicidize the array.
- Used STM measurements to show the transition from barrier limited to transport limited behavior
- Verified Field emitter performance in large gap system



D. Jonker

Mesoscale chemical systems (MCS)/

Physics of Interfaces and Nanomaterials (PIN)

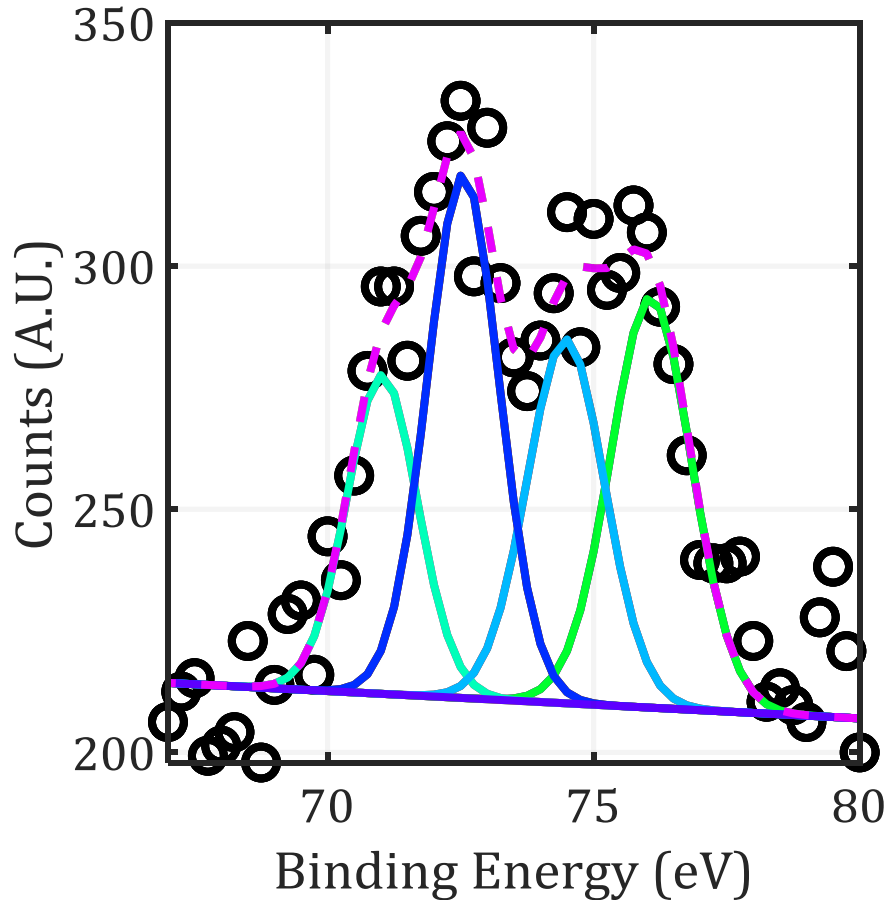
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1. Ağiral, et al., "Charge injection from carbon nanofibers into hexane under ambient conditions," 2011.
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4. Manish K. Niranjana et al. 'Theoretical investigation of PtSi surface energies and work functions'. Phys. Rev. B. (2006)
5. M. Baiet al. 'Asymmetric bias-induced barrier lowering as an alternative origin of current rectification in geometric diodes'. Nat. Com.PhysB. (2021)
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- 8.

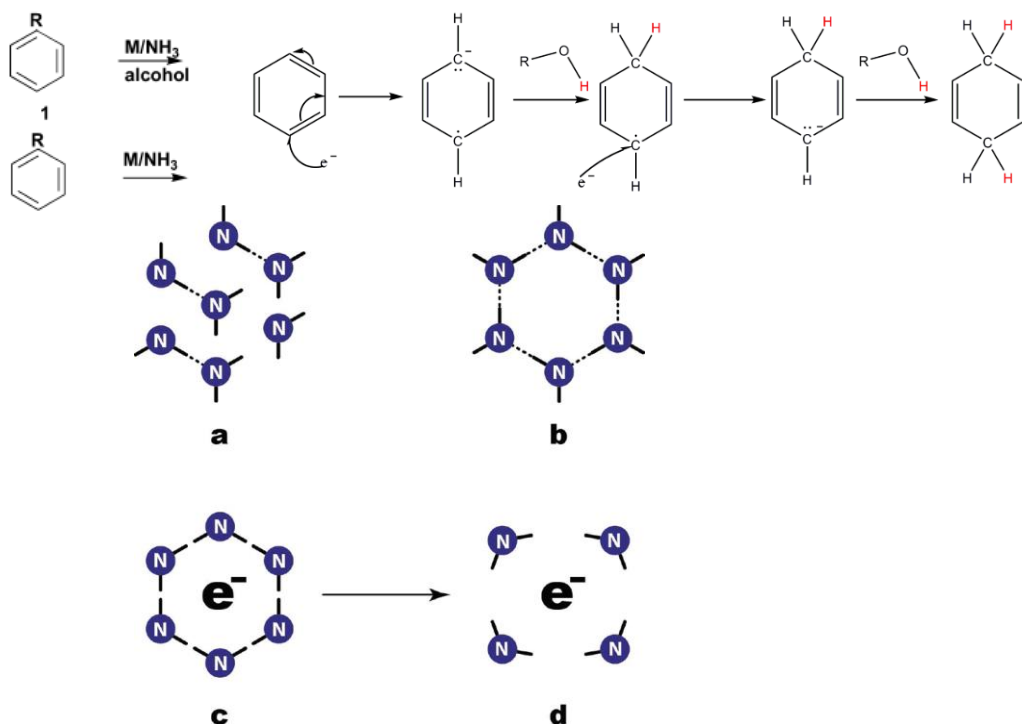
XPS data on PtSi

	Pt4f _{5/2}		Pt _x Si _{1-x}	Pt4f _{7/2}
Position	76.1	71.0	74.5	72.5
FWHM	1.8	1.6	1.7	1.6
Area	163	111	139	185
Lineshape	GL(20)	GL(20)	GL(20)	GL(20)

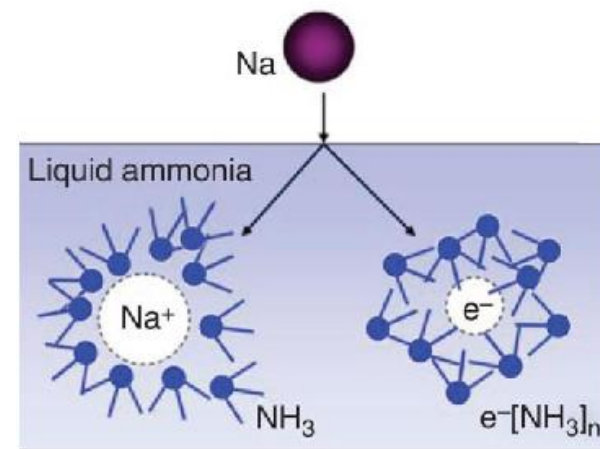


The solvated electron

Classic Birch Reduction

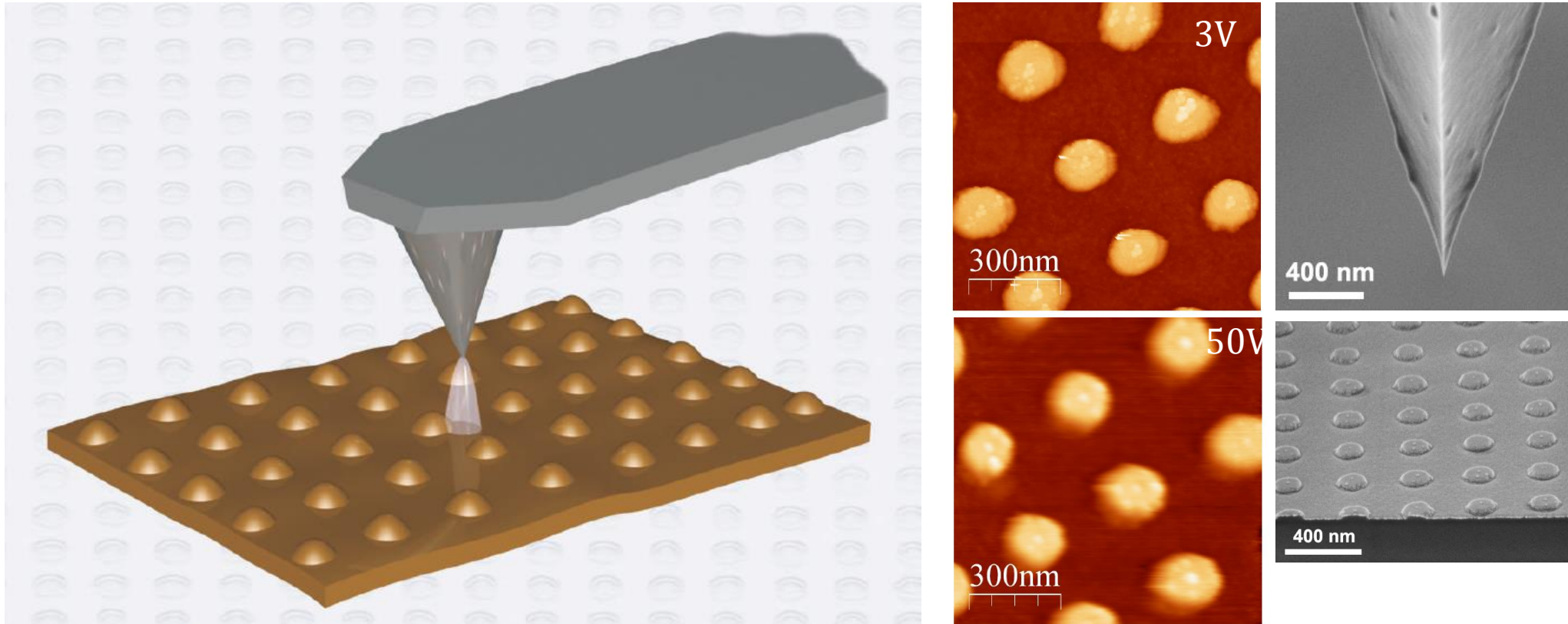


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Moving towards the substrate

